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Renesas Electronics Corporation

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M65762FP

QM-Coder

REJ03F0235-0200

Rev.2.00

Sep 14, 2007

Description

The M65762FP is a compression and decompression LSI conforming to the high efficiency encoding system (QM-Coder) in the International Standard, the JBIG/JPEG (ITU-T Recommendations T.81 and T.82) for coding still images. It also conforms to the International Standard (ITU-T Recommendation T.85) for facsimile.

The QM-Coder is an information dependent type which is capable of completely restoring original image data, and is equipped with the learning function to always optimize parameters according to the statistical characteristics of images. The QM-Coder is therefore superior in compression ratio compared with the existing binary coding system (MH/MR/MMR) and can greatly improve the half toning image (dithered half toning image) whose compression ratio is especially poor.

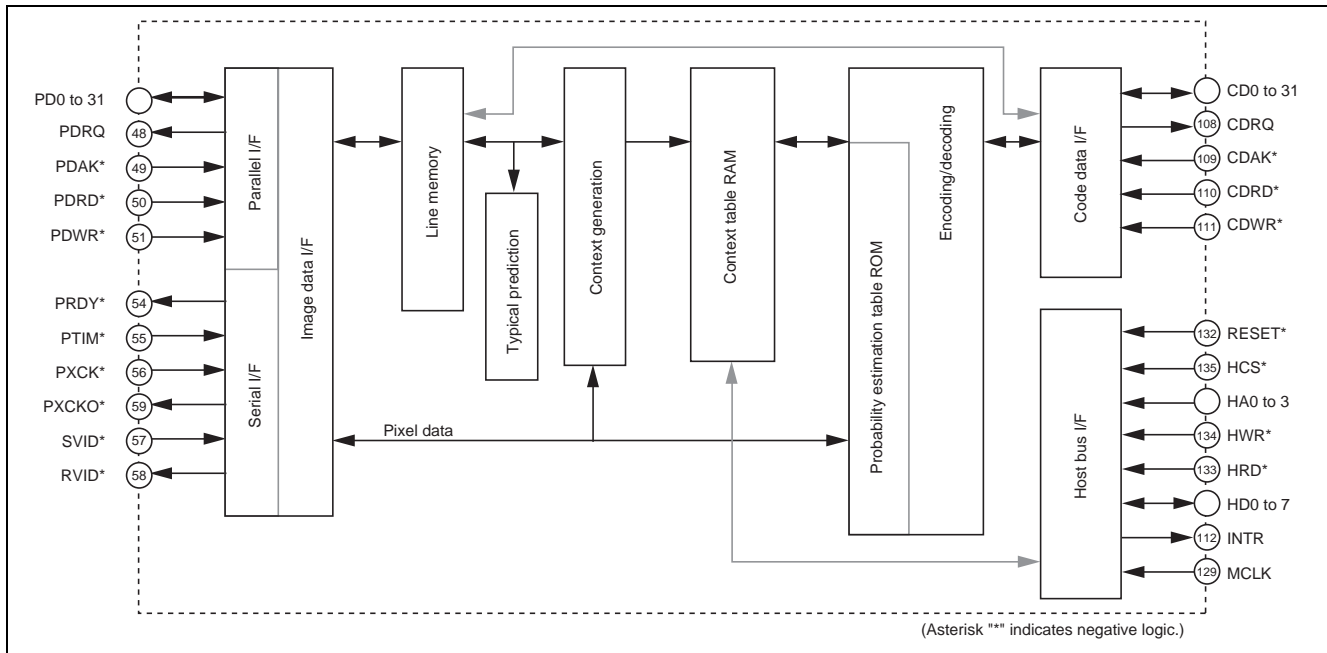
Features

- Completely conforms to the International Standard (ITU-T T.85) for facsimile.
- Achieves encoding/decoding with the arithmetic coder (QM-Coder) conforming to the recommendation of the International Standard JBIG/JPEG.
- Is expected to conform to the International Standard for color facsimile (T. Palette-colour).
- High speed processing that puts into effect coding and decoding at 40 million pixels per second maximum.
- Is possible data-through processing without coding and decoding.
- Can select context
 - Provides 10 pixel template model for minimum resolution conforming to JBIG and can select 2-line or 3-line template model.
- Built-in typical prediction function
 - Capable of coding and decoding by using the typical prediction.
 - Since use of the typical prediction does not require the processing of the line (TP line) which is matched the previous line's data, is capable of reducing data and processing time.
- Built-in adaptive template (AT) function
 - Is capable of setting AT pixels before 127 pixels on the coding line.
 - Since it is possible to change the position of AT pixel in a specified line, is capable of improving compression characteristics even when image characteristic is changed in the middle of the screen.
- Supporting multi-stripe
 - When a page consists of more than one stripe, is capable of repeating encoding/decoding process in stripes.
- Built-in load/store function of line memory → Supporting multiple planes and multi-stripe function
 - Is capable of loading image data for reference line from outside to line memory of the LSI and storing image data from line memory to outside.
- Number of processing lines
 - Is capable of issuing the start of processing (temporary stop command) several times to encode/decode any lines more than or equal to 65535 lines.
- Supporting 3-bus interface
 - An 8-bit host bus corresponds to the MPU is available to load and store of context table RAM.
 - For input/output of binary image data, is capable of performing 32-bit or 16-bit parallel or serial input/output.
 - For input/output of coding data, is capable of selecting 32-bit /16-bit/8-bit bus to perform DMA transfer of coding data.
- Is capable of making scale-down for coding and scale-up for decoding.
- Is capable of setting marker code for coding and detecting marker code for decoding
- Built-in RAM for 4096 bytes for line memory, built-in context table RAM and built-in probability estimation table ROM of 113 status
- +5 V single power supply

Application

- OA equipment including facsimile, copier and printer
- Digital and amusement equipment for the purpose of reducing memory

Block Diagram



Description on Block Functions

(1) Host bus I/F block

This bus is used to set command parameters and load the status between the MPU and this block. It is 8-bit bus. This block is also available to load and store of context table RAM via the host bus.

(2) Code data I/F block

Bus for input/output of coding data. For the bus width, 32 bits, 16 bits or 8 bits can be selected.

Image data can also be transferred (in through mode) between the image data I/F and this block via built-in line memory. FIFO buffer for 16 bytes are provided in the code data I/F block.

(3) Image data I/F block

The Image data I/F is used for input/output of binary image data. The 32-/16-bit parallel I/F or serial I/F can be selected. Selection of the serial I/F transfers data in units of 1 pixel in synchronization with the line, using the handshake signal (PRDY*, PTIM*).

Selection of parallel I/F uses an external DMA controller for DMA transfer (in units of stripe).

The image data I/F provides a function for scale-down of length and breadth by 1/2 in coding and a function for scale-up of length and breadth by twice in decoding.

(4) Line memory block

4 K-byte memory. This block can be set to a maximum of 8192 pixels/line for 3-line template and can be set to a maximum of 10240 pixels/line for 2-line template. A line is used for input/output processing of image data to/from outside and the other lines (2 or 3 lines) are used for encoding/decoding processing. These two processes can be independently carried out in synchronization with each line.

The contents of line memory can be loaded or stored via the image data I/F or coding data I/F.

(5) Typical prediction block

In the typical prediction mode, compares the encoding/decoding process line agree with the immediately preceding line and generates pseudo-pixel (SLNTP).

(6) Context generator

By using the 10-pixel template of 2-lines or 3-lines, (including AT pixel) the standard context minimum of JBIG is generated with the resolution.

(7) Context table RAM block

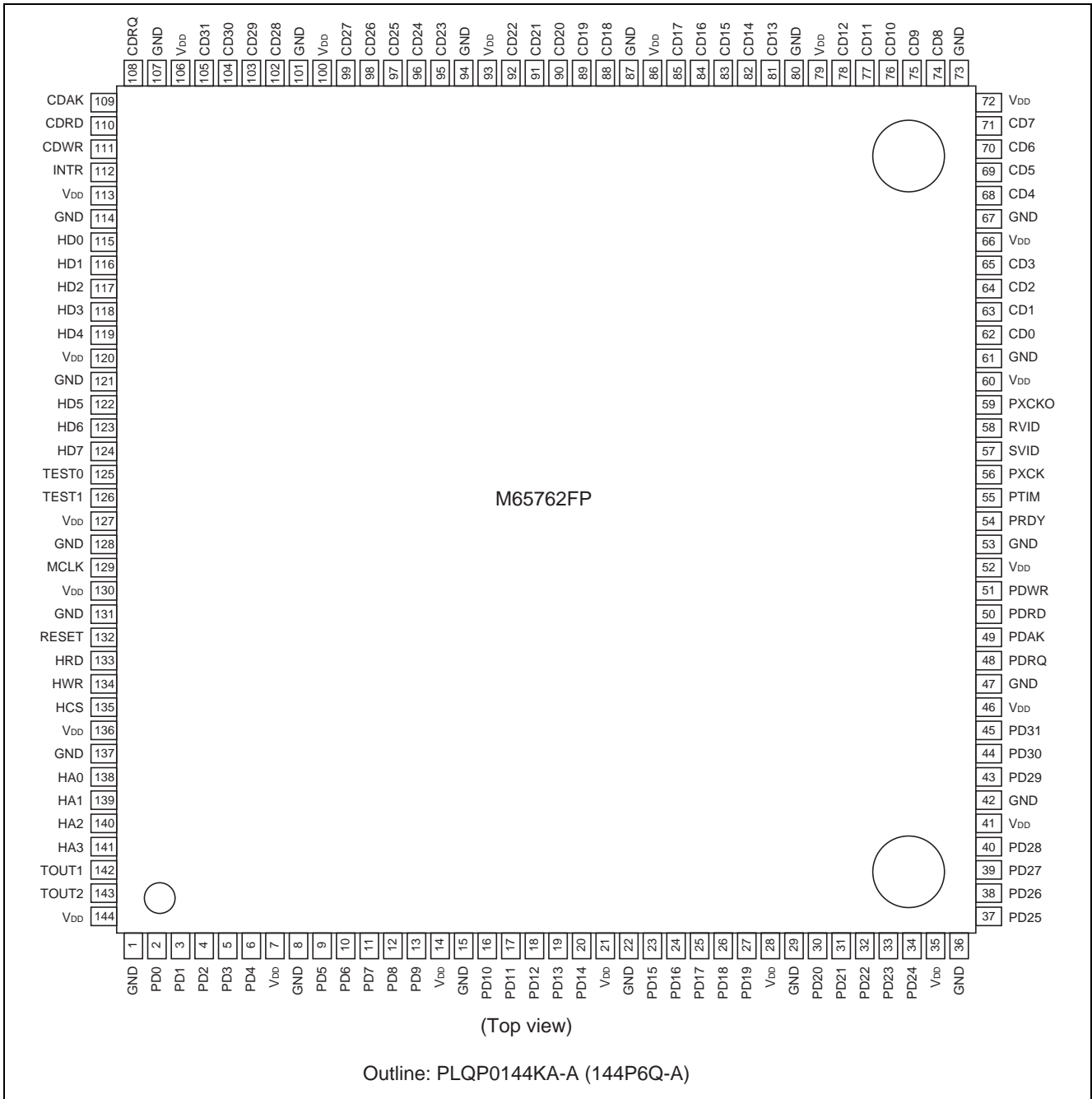
Corresponds to the 10-bit standard context. This block can initialize, load and store the context table RAM.

(8) Coding/decoding block

This block performs arithmetic coding and decoding.

It contains a ROM which contains a table capable of estimating 113 states and is capable of byte stuffing function ('OO' byte insertion/rejection) and is capable of end marker code control (Marker insertion/detection).

Pin Arrangement



Pin Description

Pin No.	I/O	Pin Name	Pin No.	I/O	Pin Name	Pin No.	I/O	Pin Name
1	Power supply	GND	51	I	PDWR	101	Power supply	GND
2	I/O	PD0	52	Power supply	V _{DD}	102	I/O	CD28
3	I/O	PD1	53	Power supply	GND	103	I/O	CD29
4	I/O	PD2	54	O	PRDY	104	I/O	CD30
5	I/O	PD3	55	I	PTIM	105	I/O	CD31
6	I/O	PD4	56	I	PXCK	106	Power supply	V _{DD}
7	Power supply	V _{DD}	57	I	SVID	107	Power supply	GND
8	Power supply	GND	58	O	RVID	108	O	CDRQ
9	I/O	PD5	59	O	PXCKO	109	I	CDAK
10	I/O	PD6	60	Power supply	V _{DD}	110	I	CDRD
11	I/O	PD7	61	Power supply	GND	111	I	CDWR
12	I/O	PD8	62	I/O	CD0	112	O	INTR
13	I/O	PD9	63	I/O	CD1	113	Power supply	V _{DD}
14	Power supply	V _{DD}	64	I/O	CD2	114	Power supply	GND
15	Power supply	GND	65	I/O	CD3	115	I/O	HD0
16	I/O	PD10	66	Power supply	V _{DD}	116	I/O	HD1
17	I/O	PD11	67	Power supply	GND	117	I/O	HD2
18	I/O	PD12	68	I/O	CD4	118	I/O	HD3
19	I/O	PD13	69	I/O	CD5	119	I/O	HD4
20	I/O	PD14	70	I/O	CD6	120	Power supply	V _{DD}
21	Power supply	V _{DD}	71	I/O	CD7	121	Power supply	GND
22	Power supply	GND	72	Power supply	V _{DD}	122	I/O	HD5
23	I/O	PD15	73	Power supply	GND	123	I/O	HD6
24	I/O	PD16	74	I/O	CD8	124	I/O	HD7
25	I/O	PD17	75	I/O	CD9	125	I	TEST0
26	I/O	PD18	76	I/O	CD10	126	I	TEST1
27	I/O	PD19	77	I/O	CD11	127	Power supply	V _{DD}
28	Power supply	V _{DD}	78	I/O	CD12	128	Power supply	GND
29	Power supply	GND	79	Power supply	V _{DD}	129	I	MCLK
30	I/O	PD20	80	Power supply	GND	130	Power supply	V _{DD}
31	I/O	PD21	81	I/O	CD13	131	Power supply	GND
32	I/O	PD22	82	I/O	CD14	132	I	RESET
33	I/O	PD23	83	I/O	CD15	133	I	HRD
34	I/O	PD24	84	I/O	CD16	134	I	HWR
35	Power supply	V _{DD}	85	I/O	CD17	135	I	HCS
36	Power supply	GND	86	Power supply	V _{DD}	136	Power supply	V _{DD}
37	I/O	PD25	87	Power supply	GND	137	Power supply	GND
38	I/O	PD26	88	I/O	CD18	138	I	HA0
39	I/O	PD27	89	I/O	CD19	139	I	HA1
40	I/O	PD28	90	I/O	CD20	140	I	HA2
41	Power supply	V _{DD}	91	I/O	CD21	141	I	HA3
42	Power supply	GND	92	I/O	CD22	142	O	TOUT1
43	I/O	PD29	93	Power supply	V _{DD}	143	O	TOUT2
44	I/O	PD30	94	Power supply	GND	144	Power supply	V _{DD}
45	I/O	PD31	95	I/O	CD23			
46	Power supply	V _{DD}	96	I/O	CD24			
47	Power supply	GND	97	I/O	CD25			
48	O	PDRQ	98	I/O	CD26			
49	I	PDAK	99	I/O	CD27			
50	I	PDRD	100	Power supply	V _{DD}			

- Notes:
1. Directly connect the input pin having pull-up (see "Description on Pin Functions") to V_{CC} when the pin is not used.
 2. Directly connect the input pin having pull-down (see "Description on Pin Functions") to GND when the pin is not used.
 3. Connect test input pin TEST 0/1 to GND.
 4. Leave test output pin TOUT 1/2 open.

Description on Pin Functions

(Asterisk "*" in signal name indicates negative logic.)

I/F	Pin Name	I/O	BUF	Function	
Host bus I/F	RESET*	I	S	H/W reset signal	
	HCS*	I		Chip select signal	
	HA0 to 3	I		Address select signal of internal register	
	HWR*	I	S	Write strobe signal	
	HRD*	I	S	Read strobe signal	
	HD0 to 7	I	R8	Input/output data bus signal	
	INTR	O	4	Interrupt request signal	
Code data I/F	CD0 to 31	I/O	UR8	Coding data input/output bus signal (CD0 to 15 is used in 16-bit bus and CD0 to 7 is used in 8-bit bus.)	
	CDRQ	O	4	DMA request signal for coding data (image data)	
	CDAK*	I	US	DMA acknowledge signal for coding data (image data)	
	CDRD*	I	US	Read strobe signal for coding data (image data)	
	CDWR	I	US	Write strobe signal for coding data (image data)	
Image data I/F	Parallel	PD0 to 31	I/O	UR8	Parallel image data input/output bus (PD0 to 15 is used in 16-bit bus.)
		PDRQ	O	4	DMA request signal for image data
		PDAK*	I	US	DMA acknowledge signal for image data
		PDRD*	I	US	Read strobe signal for image data
		PDWR*	I	US	Strobe signal for image data
	Serial	PRDY*	O	4	1-line input/output start ready signal for image data
		PTIM*	I	US	1-line transfer sector signal for image data
		PXCK*	I	US	Transfer clock signal for image data
		PXCKO*	O	4	Transfer clock signal for image data (LSI internal loop back output signal of PXCK*)
		SVID*	I	U	Image data input signal
RVID*	O	4	Image data output signal		
Others	MCLK	I		Master clock input signal	
	TEST0, 1	I	DS	Test input signal 0/1 (Should be connected to GND when used normally.)	
	V _{DD}	—	—	Power supply (+5 V)	
	GND	—	—	Ground	

Note: Input buffer for the input pins ("I" and "IO") are set at the TTL level and the options are as follows.
(U: Having pull-up resistance, D: Having pull-down resistance, S: Schmitt trigger, R: Through rate control)
Numbers (4, 8) in the BUF column for the output pins ("O" and "IO") indicate I_o (= 4 or 8 mA).

Specifications

- (1) Package
Plastic QFP 144 pins (20 mm × 20 mm)
- (2) Power consumption
5 V, 120 mA (600 mW)
- (3) Maximum clock frequency
40 MHz

Specifications of Coding Functions

(1) Coding algorithm

- QM-Coder (JBIG standard arithmetic coding system)

(2) Context

a) Template model

- 2- or 3-line of 10-pixel template (see figure 1)
(Conforming to the template for JBIG minimum resolution)
Note: The coding efficiency of the 3-line template is better than that of 2-line template by several %.

b) Adaptive template (AT)

- It is possible to move up to 127 pixels on the coding line.
(AT position is indicated by MPU.)
Note: AT is available to improve the coding efficiency for dither image.
- Even in the middle of coding/decoding, the position of AT line can be changed for a line (AT move)
Note: When the position the AT pixel of is changed, the template model cannot be changed concurrently.

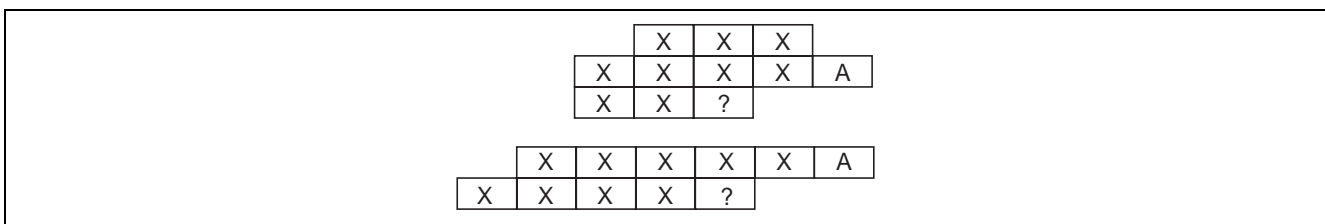


Figure 1 Template (X, A) (Upper: 3 lines, Lower: 2 lines)

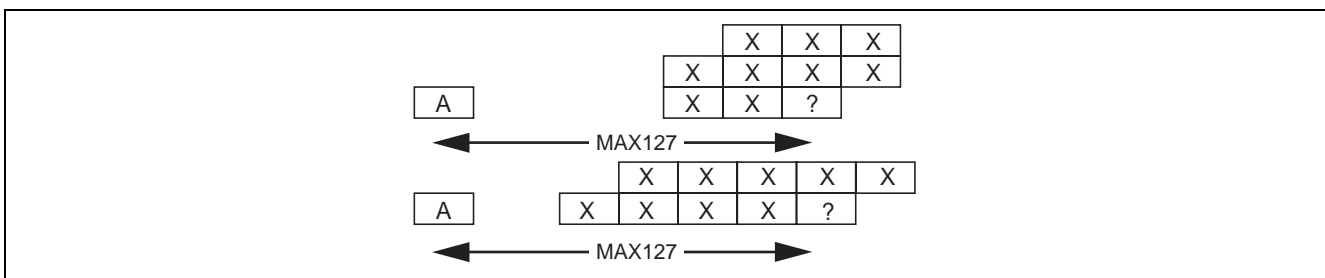


Figure 2 Adaptive Template (A)

(3) Typical prediction

- Agreement with the typical prediction of the minimum resolution of JBIG.
The pseudo-pixel (SLNTP) is generated by the symbol LNTP which shows whether the coding/decoding process lines agree with the immediately preceding line. If they agree, the pseudo-pixel only is coded. This makes it possible to shorten the time of process and rejection of the code data.

$$SLNTP_y = ! (LNTP_y \oplus LNTP_{y-1})$$

(Where: y indicates a line No., y = 1 indicates that lines do not match each other, and initial value LNTP for head line is given with y - 1 = 1)

(4) Coding data format

- The stripe data entity.

(SDE = stripe coded data with byte stuffing (PSCD) + end marker (SDNORM/SDRST))

Performs coding and decoding of one stripe (see "Appendix A.1")

In the case of multi-stripped (multi-stripes), can be supported by activation for each stripe.

(5) Marker code

- Supports the SDE end marker
(During coding, the marker code previously set in the register is outputted. During decoding, the marker code byte detected by requesting an interrupt to MPU when the marker is detected is read out of the register.)

(6) Estimation of coding/decoding speed

Figure 3 compares the estimation of coding/decoding speed between the M65762FP and the existing product type (M65760/1FP). Polygonal lines in the diagram are processing speeds of images theoretically generated assuming the unmatched estimation ratio as a parameter. In addition, ○□△ indicate processing speeds of real image (without TP function).

As shown in this diagram, the M65762FP has been largely improved in the processing speed compared with existing product types. If the compression ratio is reduced, the reduction ratio of processing speed is moderated.

When a theoretical image is used to compare processing speeds in the worst case, the processing speed of existing product type is about 9.4 M pixels/s (1 / compression ratio ≈ is about 1), while the processing speed of the M65762FP is about 27.5 M pixels/s (1 / compression ratio ≈ 0.9) for coding and is about 31.2 M pixels/s (1 / compression ratio ≈ 0.75) for decoding.

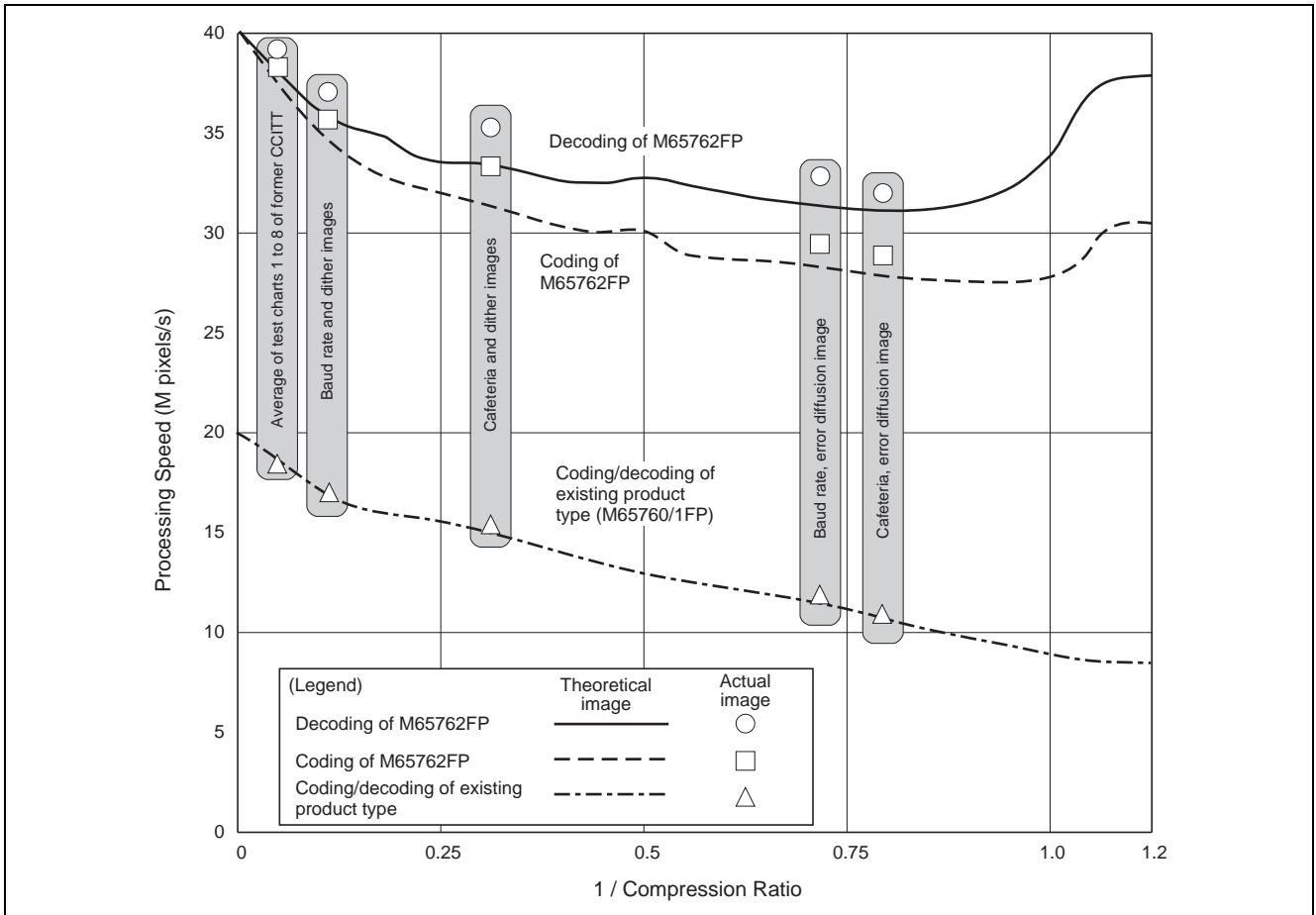


Figure 3 Estimated Processing Speed

Register Configuration

1. List of Registers

Table 1 List of Registers

Address	Register Name	R/W	Content
0	System setting	W/R	<ul style="list-style-type: none"> LSI H/W reset Selects bit width of code data bus (32 bits/16 bits/8 bits) Selects coding (image) data byte swap on code data bus Selects coding (image) data bit swap on code data bus Selects image data bit swap on image data bus Selects image data I/F (parallel I/F and serial I/F) Selects bit width of image data bus (32 bits/16 bits)
1	Parameter setting	W/R	<ul style="list-style-type: none"> Template selection (3-line template/2-line template) Sets up the AT pixel position (127 max) (When set to 0, selects non-AT (default position))
2	Command	W	<ul style="list-style-type: none"> Context table RAM initializing processing command Start/stop command (Coding/decoding, image data through, load/store of the line memory) Start/stop command of load/store of context table RAM Selects temporary stop/termination end mode
2	Status	R	<ul style="list-style-type: none"> Processing status (in process/end of process) Ready for reading/writing coding (image) data on code data bus Detects marker code (SDNORM, SDRST, ABORT, etc) Interrupt request status SC counter overflow error Processing mode (temporary stop/end of termination)
3	Interrupt enable setting	W/R	<ul style="list-style-type: none"> Interrupt enable setting corresponding to each bit position of status register Indicates pause/restart with marker code detected (at time of decoding)
4, 5	Setting number of pixels	W/R	<ul style="list-style-type: none"> Sets the number of pixels per line (a maximum of 10240 pixels with 2-line template selected)
6, 7	Setting number of lines	W/R	<ul style="list-style-type: none"> Sets the number of lines to be coded/decoded (1 line or more, a maximum of 65535 lines)
8, 9	Number of processing lines	R	<ul style="list-style-type: none"> Number of setting the coded/decoded lines (a maximum of 65535 lines)
A	Load/store buffer	W/R	<ul style="list-style-type: none"> Buffer register that loads/stores context table RAM data from the MPU (RAM address is automatically incremented each time data is written/read.)
B	Operation mode setting	W/R	<ul style="list-style-type: none"> Sets the operation mode (Coding/decoding, image data through, and load/store of line memory) Selects read-through of head coding data in decoding (0 to 3 bytes) Selects the typical prediction function Selects prohibition of line memory initialization
C	Marker code setting	W	<ul style="list-style-type: none"> Sets the terminal marker code in encoding (SDNORM/SDRST)
C	Marker code reading	R	<ul style="list-style-type: none"> Reads a marker code in decoding (SDNORM, SDRST, ABORT, others)
D	Scale-up/scale-down setting	W/R	<ul style="list-style-type: none"> Scale down in coding (1/2 scale-down of horizontal and vertical, horizontal OR processing) Scale-up at time of decoding (scale-up of horizontal and vertical by twice)

2. Description on Register

(1) System setting register (W/R)

(Address: 0)	d7(MSB)						d0 (LSB)	
SYS_REG:	PB	PI	BX	BS	DS	CB	HR	

d0 (HR): H/W reset (0: Active status, 1: Reset status)

To reset H/W, set this bit to 1 then to 0. The entire LSI including register group and line memory is initialized by writing in this reset. However, context table RAM is not initialized.

d1 to 2 (CB): Selects the bit width of code data bus

(d2 = 0, d1 = 0: 8-bit bus (CD0 to 7), d2 = 0, d1 = 1: 16-bit bus (CD0 to 15), d2 = 1, d1 = 0: 32-bit bus (CD0 to 31))

Notes: 1. Prohibition of setting for d2 = 1, d1 = 1

2. For encoding in 16-/32-bit bus, the last encoding data is output followed by bit byte of "00" (3 bytes maximum) for word alignment of encoding data at the end.

d3 (DS): Selects data bit swap of image data bus (0: MSB first, 1: LSB first) → see table 3.

d4 (BS): Selection of data bit swap of code data bus (0: MSB first, 1: LSB first) → see table 2.

d5 (BX): Selection of data byte swap of code data bus

(0: low order byte first, 1: high order byte first) → see table 2.

Note: BX is effective only when the host bus selects 16-bit/32-bit bus.

d6 (PI): Selection of image data input/output I/F (0: serial I/F, 1: parallel I/F)

d7 (PB): Selection of bit width of image data bus

(0: 32-bit bus (PD0 to 31), 1: 16-bit bus (PD0 to 15)) → see table 3.

Note: PB and DS are effective only when PI = 1.

Table 2 Line Up of Coded Data/Image Data in Code Data Bus

Bus Width (CB)		Swap (BX, BS)		Order of Data in Code Data Bus (CD)											
d2	d1	d5	d4	CD31	...	CD24	CD23	...	CD16	CD15	...	CD8	CD7	...	CD0
1	0	0	0	b24	...	b31	b16	...	b23	b8	...	b15	b0	...	b7
		0	1	b31	...	b24	b23	...	b16	b15	...	b8	b7	...	b0
		1	0	b0	...	b7	b8	...	b15	b16	...	b23	b24	...	b31
		1	1	b7	...	b0	b15	...	b8	b23	...	b16	b31	...	b24
0	1	0	0	—	—	—	—	—	—	b8	...	b15	b0	...	b7
		0	1	—	—	—	—	—	—	b15	...	b8	b7	...	b0
		1	0	—	—	—	—	—	—	b0	...	b7	b8	...	b15
		1	1	—	—	—	—	—	—	b7	...	b0	b15	...	b8
0	0	—	0	—	—	—	—	—	—	—	—	—	b0	...	b7
		—	1	—	—	—	—	—	—	—	—	—	—	b7	...

Note: b0 is image data, given in time series, on the left side of the first encoding data/screen. b31 is image data, given in time series, on the right side of the last encoding data/screen.

Table 3 Order of Image Data on Image Data Parallel Bus

Bit Width	Swap	PD31	PD16	PD15	PD0
PB = 0	DS = 0	p0	p15	p16	p31
	DS = 1	p31	p16	p15	p0
PB = 1	DS = 0	—	—	—	p0	p15
	DS = 1	—	—	—	p15	p0

Note: p0 is image data on the left side of the screen. p31 is image data on the right side of the screen.

(2) Parameter setting register (W/R)

(Address: 1)	d7	d6	d5	d4	d0	
PARA_REG:	AT		TM	AT		

d0 to 4 (AT<0> to AT<4>): Low order 5 bits of AT pixel position (see figure 2)

d5 (TM): Selection of template (0: 3-line template, 1: 2-line template)

d6 to 7 (AT<5> to AT<6>): High-order 2 bits of AT pixel position (6th/7th bit)

(Example)	d7	d4					d0	
3-line template, AT = 4	0	0	0	0	0	1	0	0
2-line template, AT = 48	0	1	1	1	0	0	0	0

Note: AT pixel position is set (0 to 127) with AT<6:0>. At the default position (AT pixel is not used), set AT = 0. The 2-line template, prohibits AT = 1 to 4 from being set. The 3-line template prohibits AT = 1 to 2 from being set.

(3) Command register (W)

(Address: 2)	d7	d3			d0	
CMD_REG:	0		JP	RC	JC	IC

d0 (IC): Context table RAM initialization start command (1: Start initialization)

Setting this bit to 1 starts to initialize context table RAM.

When the initialization is completed automatically returns this bit to 0.

d1 (JC): Processing (coding/decoding/through) start/end command (1: Start of processing, 0: End of processing)

Setting this bit to 1 starts processing (coding/decoding, image data through and lead/store of line memory).

Before the issuance of this command, concrete operation mode must be set in the operation mode setup register.

When the processing for the number of setup lines ends with the end of termination selected this bit automatically returns to 0.

Note: When this JC bit is set to 0 during the coding process (is in progress,) and input of image data is stopped, the coding is stopped (flushed) even if the set lines are not filled. When this bit is set to 0 during decoding process, and input of encoding data ceases, processing for the number of setup lines is carried out assuming coding data "00" to have been input. In the case of multi-stripe coding, however, process must not be stopped by setting this bit to 0 except for the final stripe.

d2 (RC): Load/store start/end command of context table RAM (1: Start of load/store, 0: End of load/store)

Setting this bit to 1 can load context data into context table RAM from outside via a buffer register or can store context data in outside. (see the section for buffer register.)

When load/store processing is completed, this bit must be set to 0.

d3 (JP): Temporary stop mode of processing (coding/decoding/through)/termination end mode selection

(1: Selection of temporary stop, 0: Selection of termination end)

Issuance of processing start command d1 (JC) with this JP bit set to 1 temporarily stops performing the process operation at the completion of processing for the number of setup lines. After that, reissuance of processing start command d1 (JC) restarts processing. (see "Register Setting Sequence" (3))

(4) Status register (R)

(Address: 2)	d7	d5					d0	
STAT_REG:	0	PS	SC	IS	MS	DS	JS	

- d0 (JS): Processing (initialization/coding/decoding/through) status
(0: Processing in progress (temporary stop or initial), 1: Completion of processing)
This JS bit is set to 1 in the following cases: when the initialization is complete with the RAM initialization command issued (IC = 1), when all coding data is read completely at time of coding with the start command of termination end processing issued (JC = 1, JP = 0), and when all image data is read completely at time of image data through and at time of decoding. When the temporary stop processing start command is issued (JC = 1, JP = 1), this JS bit remains to be 0, even if the process for the number of setup lines ends. (However, an interruption occurs at time of temporary stop.)
- d1 (DS): Ready for reading/writing coding data (image data case of the through mode) on the code data bus
(1: Ready, 0: Read/write disabled)
When this bit is set to 1, data can be read/written on the code data bus. (This bit is equivalent to the CDRQ pin.)
- d2 (MS): Detects marker code at time of decoding (0: Not detected, 1: Detected)
This bit is set to 1 when some marker code is detected at time of decoding.
- d3 (IS): Status of interrupt request (INTR pin) (0: Not requested, 1: Requested)
- d4 (SC): SC count-over error at time of coding (0: Normal, 1: Occurrence of SC counter overflow)
Note: The SC counter is a counter for consecutive "FF" data bytes generated in the coding process. Though coding process continues if the SC counter overflows, normal coding data is not output (encoding error).
- d5 (PS): Processing (temporary stop/termination end) mode
(1: Temporary stop processing mode, 0: Termination end processing mode)
This PS bit corresponds to the selection of process temporary stop/termination end of the d3 (JP) bit of command register.

(5) Interrupt enable register (W/R)

(Address: 3)	d7	d3				d0
IENB_REG:	MP	0	SE	ME	DE	JE

- d0 (JE): Processing (initialization/coding/decoding/through)
Temporary stop/termination end interrupt (0: Interrupt mask, 1: Interrupt enable)
- d1 (DE): Coding data (image data) read/write ready interrupt (0: Interrupt mask, 1: Interrupt enable)
- d2 (ME): Marker code detection interrupt at time of decoding (0: Interrupt mask, 1: Interrupt enable)
- d3 (SE): SC count-over error interrupt at time of coding (0: Interrupt mask, 1: Interrupt enable)
Note: Bits d0 to d3 are interrupt enable of bits d0 to d2 and d4 corresponding to the status register. When one of the status bits set to interrupt enable is set to 1, the interrupt request signal (INTR) is asserted (for d0 (JE), an interrupt occurs even at the time of temporary stop). When the status is set to 0 by H/W reset etc., or when interrupt factor is eliminated by interruption masking, INTR is negated. The status register is not cleared by occurrence of interruption or by R/W of interruption enable register.

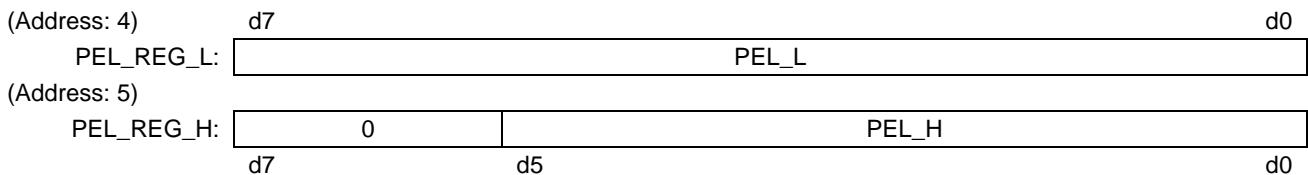
d7 (MP): Indication of pause at time of marker code detection
(0: Indication of continuation/restart, 1: Indication of temporary pause)

If this MP bit is in advance set to 1 in decoding, the decoding temporarily pauses at the time of marker code detected.

(When the ME bit is set to 1, an interruption occurs when marker code is detected.)

When decoding process is not completed at time of temporary pause of marker detection, the register for setting the number of lines can be respecified (see item (7)). Afterwards, setting this MP bit to 0 restarts the decoding process (the decoding process is carried out for the number of set lines).

(6) Register for setting the number of pixels (W/R)



d0 to 7 (PEL_L): Sets the number of pixels in a line. (Low byte)

d0 to 5 (PEL_H): Sets the number of pixels in a line. (Upper byte)

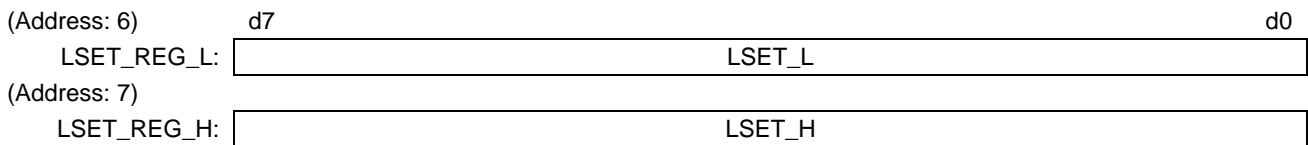
A maximum of 8192 pixels can be set at the 3-line template. A maximum of 10240 pixels can be set at the 2-line template.

Set the number of pixels to be actually coded (decoded) at time of scale-up (scale-down).

When the image data bus is 16 bits (32 bits) with the parallel I/F selected, set the number of pixels to multiples of 16 (multiples of 32).

With the serial I/F selected, set the number of pixels to multiples of 8.

(7) Register for setting the number of lines (W/R)



d0 to 7 (LSET_L): Sets the number of lines to be processed. (Low order byte) (1 to 65535: 0 line is not allowed.)

d0 to 7 (LSET_H): Sets the number of lines to be processed. (High order byte)

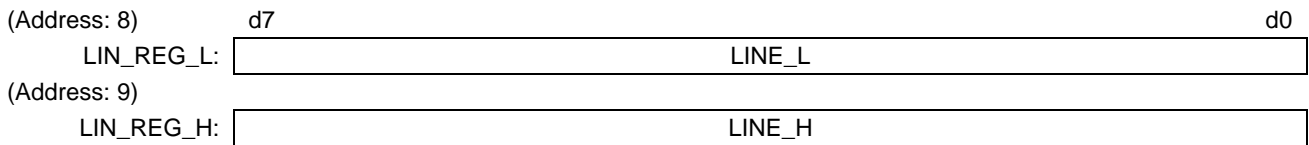
At time of scale-down (scale-up), set the number of lines to be actually coded (decoded).

Set the number of lines (number of relative lines) ranging from the processing start command to be issued next to the temporary stop/termination end just after. This register must be set to a specific value before the issuance of the process start command.

As far as the following conditions are satisfied, this register can be rewritten in the course of processing.

- When the maximum value (65535) is set before issuance of the processing start command, an arbitrary value can be set once in the course of processing.
- When a value except for the maximum value (65535) is set before issuance of the processing start command, and the value requires to be respecified in the course, respecify the maximum value (65535) once and then respecify a desired value.

(8) Processing line count register (R)



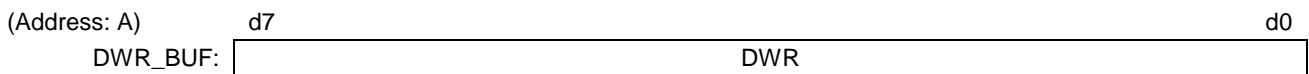
d0 to 7 (LINE_L): Read out the number of lines actually processed (Low byte) (0 to 65535)

d0 to 7 (LINE_H): Read out the number of lines actually processed (Upper byte)

The number of processed lines number of set lines, coding/decoding/through processing stop temporary/end of processing.

Note: The number of lines in this process is cleared to 0 with the processing start command issued.

(9) Buffer register (W/R)

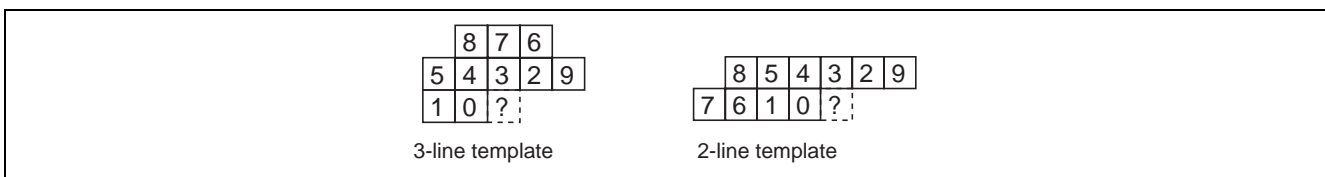


d0 to 7 (DWR): Data for loading/storing context table RAM

This register is a buffer for loading data into the context table RAM via the host bus or for storing data outside. After issuance of load/store start command of the context table RAM (command register d3 = 1), this register is available to start loading or storing data. Prediction value (MPS) and prediction unmatched probability (LSZ) can be stored in context table RAM for a unit of 1024 contexts in total. Figure 4 and table 4 provide the address assignment of context table RAM and the data bit array.

Since context table RAM is 2-byte data, access is gained alternately in order from low byte to upper byte. Each time two-byte access is gained, the RAM address is automatically incremented (sequential access from address 0).

- Notes:
1. Data is not allowed to be loaded and stored at a time. Random access to RAM is not allowed.
 2. Only 133 types specified by the JBIG international standard (see " Appendix A.2") are allowed to be specified for the LSZ value. (For example, load '5a1d' for initialization.)



**Figure 4 Address Assignment of Context Table RAM
(Number for Address Bit (LSB: 0, MSB: 9), MSB: 9 for AT Pixel)**

Table 4 Data Bit Array of Context Table RAM

High Order Byte				Low Order Byte			
d15	d14	•••••	d8	d7	•••••	d0	
MPS	L14	•••••	L8	L7	•••••	L0	

Note: MPS: Prediction value MPS (0/1)

L14 to 0: Low 15 bits of prediction unmatched probability LSZ ('0001' to '5b12')

(10) Operation mode setting register (W/R)

(Address: B)	d7				d0
MOD_REG:	TP	LI	OB	LIO	MOD

This register is used to set the LSI operation mode and requires to be set before issuance of the processing start command (command register d1 (JC) = 1).

d0, 1 (MOD): Operation mode setting
 (d1 = 0, d0 = 0: Coding, d1 = 1, d0 = 0: Image data through (image data I/F → Code data I/F) load/store, d1 = 0, d0 = 1: Decoding, d1 = 1, d0 = 1: Image data through (Code data I/F → Image data I/F) load/store)

d2, 3 (LIO): Load/store selection of image data of line memory (d2 = selection of load, d3 = selection of store)
 In the case of multi-stripe, this LIO bit is set according to the following table, to load image data for reference line from outside into line memory before coding/decoding of stripes or to store image data stored in line memory into outside after encoding/decoding of stripes. This LIO bit is effective only in the image data through mode (d1 = 1).

- Notes:
1. LIO (d3, d2) = (1, 1) not allowed being set.
 2. When selection of load/store of image data of line memory, temporary stop (d3 (JP) = 1 of command register) is not allowed to be set.
 3. When load/store mode of image data is selected, the number of lines to be transferred must be set in the register setting the number of lines.
 4. The number of lines for image data load to line memory must be 2-line either case of 2-line template or 3-line template. (This is because typical prediction (LNTP) cannot be judged correctly with only a line.)

Table 5 Operation Mode List

Operation Mode (d1, d0)	Load/Store LIO (d3, d2)	Operation Mode	Remarks
0 0	X X	Coding mode	Normal coding mode
0 1	X X	Decoding mode	Normal decoding mode
1 0	0 0	Image data through (image data I/F → code data I/F)	For inter-I/F transfer of image data
	0 1	Image data load to line memory (input from image data I/F)	For loading of reference line to LSI
	1 0	Image data store of line memory (output to code data I/F)	For storing line memory to outside
1 1	0 0	Image data through (code data I/F → image data I/F)	For inter-I/F transfer of image data
	0 1	Image data load to line memory (input from code data I/F)	For loading of reference line to LSI
	1 0	Image data store of line memory (output to image data I/F)	For storing line memory to outside

d4, 5 (OB): Sets head of the coding data read-through at time of decoding
 (0 to 3: Sets the number of read-through bytes. For example, with d4 = 0 and d5 = 1, read-through of 2 bytes)

When OB is set to 1 to 3 at time of decoding, and the first stripe decoding processing start command is issued, the head data for the number of set bytes is to be read through (not used for decoding process). With OB set to 0, no data is read through (normal decoding process).

For example, if the code data bus is 32/16 bits, and the head of coding data does not contact the word boundary, this function is used.

Note: When the code data bus is 8 bits, this function is effective.

d6 (LI): Prohibition of line memory initialization
 (0: Indication of initialization, 1: Prohibition of initialization)

When first stripe coding/decoding process start command is issued, and LI = 1, initialization of built-in line memory is prohibited.
 (The final image data, coded/decoded just before, that is left in line memory is used as the reference line data at the head of next coding/decoding operation). With LI = 0, built-in line memory is initialized. (Full white (0) data is used as the reference line data at the head of next coding/decoding operation.)

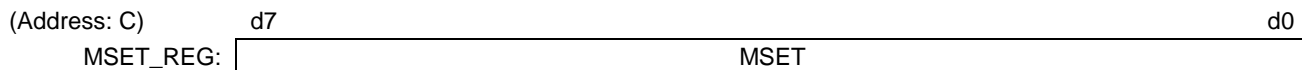
When the previous stripe is terminated at the SDNORM marker with coding/decoding of the multi-stripe configuration, this bit is set to initialization prohibition (1) to make the data of previous stripe left in line memory available as the coding reference line data of the next stripe. (For details, see " Register Setting Sequence " (6) sequence.)

Note: With LI =1, this LI bit is cleared (to 0) by H/W reset writing to an external reset pin or system setup register. At the same time, built-in line memory is also initialized.

d7 (TP): Selection of typical prediction at time of coding/decoding
 (0: Sets typical prediction function to OFF, 1: Sets typical prediction function to ON.)

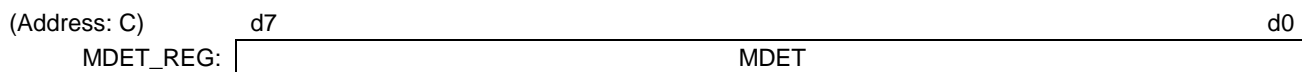
This bit is set to 1 when encoding/decoding process is carried out using the typical prediction function.

(11) Marker code set up register (W)



d0 to 7 (MSET): The end marker code used during coding is set (SDNORM = 02h, SDRST = 03h, etc.)
 The byte set to this register is output attached to coding data as the end marker during coding.

(12) Marker code read out register (R)



d0 to 7 (MDET): Reads out the marker code detected during decoding
 (SDNORM = 02h, SDRST = 03h, ABORT = 04h, etc.)

Marker code bytes detected at time of decoding can be read directly.

(13) Scale-up/scale-down set register (W/R)

(Address: D)	d7	d4				d0
CONV_REG:	0	HO	HR	VR	HE	VE

d0 (VE): Selection of scale-up in vertical direction during decoding (0: Equal size, Scale-up by twice)

d1 (HE): Selection of scale-up in horizontal direction during decoding (0: Equal size, Scale-up by twice)

Note: Scale-up function is effective only in decoding (Scale-up enabled)

d2 (VR): Selection of scale-down in vertical direction (0: Equal size, Scale-down by 1/2)

d3 (HR): Selection of scale-down in horizontal direction (0: Equal size, Scale-down by 1/2)

d4 (HO): Selection of thinned-out processing in horizontal direction (0: Simple thinned-out, 1: OR processing)

Note: Scale-down function is effective only in encoding (Scale-down enabled)

- Notes:
1. During coding, simple thinned-out is applied to 1/2 scale-down in vertical direction (Odd lines are skipped in reading.)
 2. With VR = 1 during coding, the number of lines on input image data must be larger by twice than the set value of line count setup register.
 3. With VE = 1 during decoding, the number of lines on output image data must be larger by twice than the set value of line count setup register.

3. Register Initial Value

Registers are initialized as provided in the following table by writing H/W reset into the external reset pin or system setup register.

Table 6 Initial Values of Registers

Register	Initial Value	Register	Initial Value
System setting	00h (Note)	Number of processed lines	00h
Parameter setting	00h	Buffer register	Indefinite
Command	00h	Operation mode setting	00h
Status	00h	Marker code setting	00h
Interrupt enable	00h	Marker code reading	00h
Pixel setting	00h	Scale-up/scale-down setting	00h
Line count setting	00h		

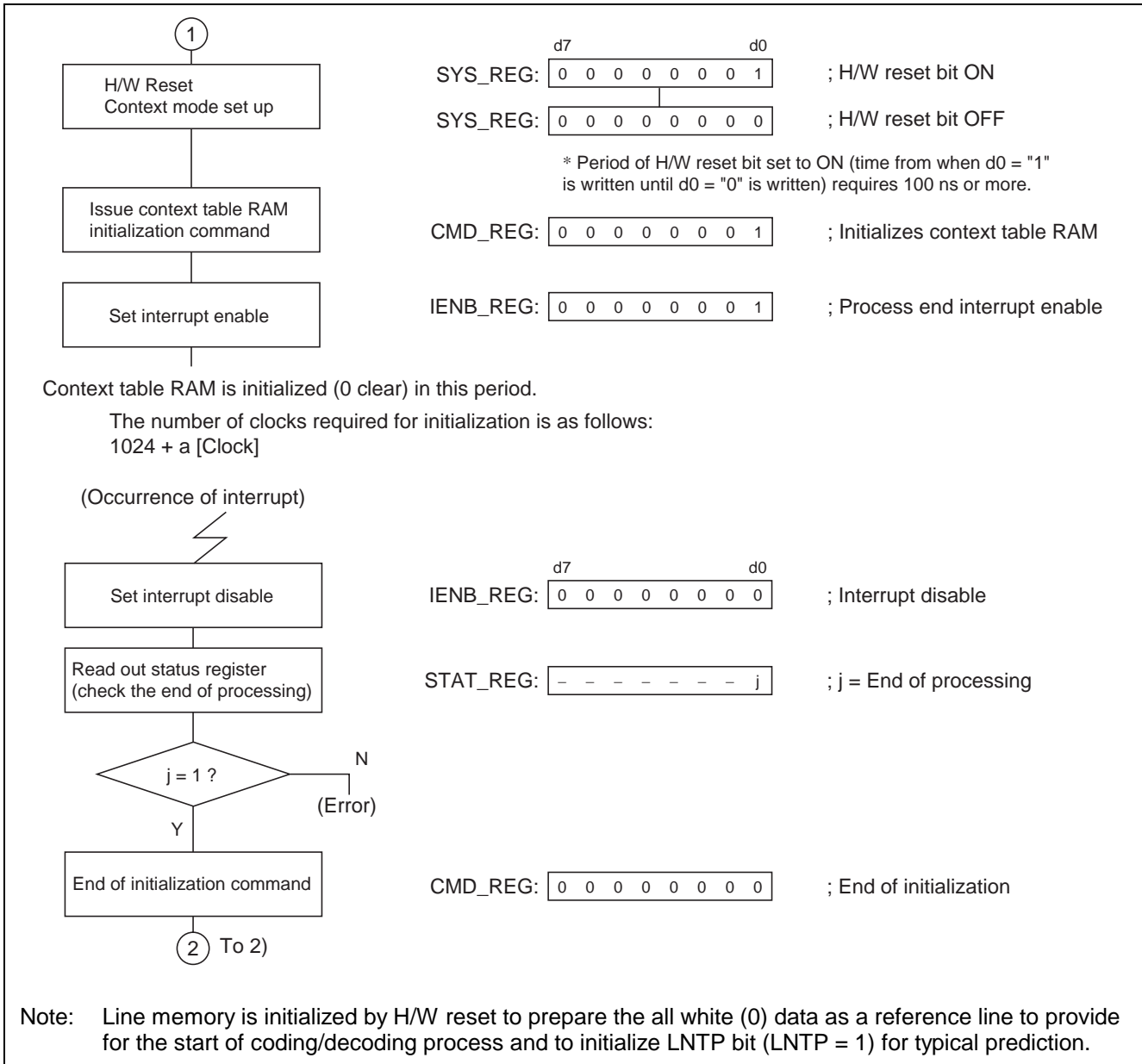
Note: When H/W reset is written into the system setting register, written value is set in the system setting register.

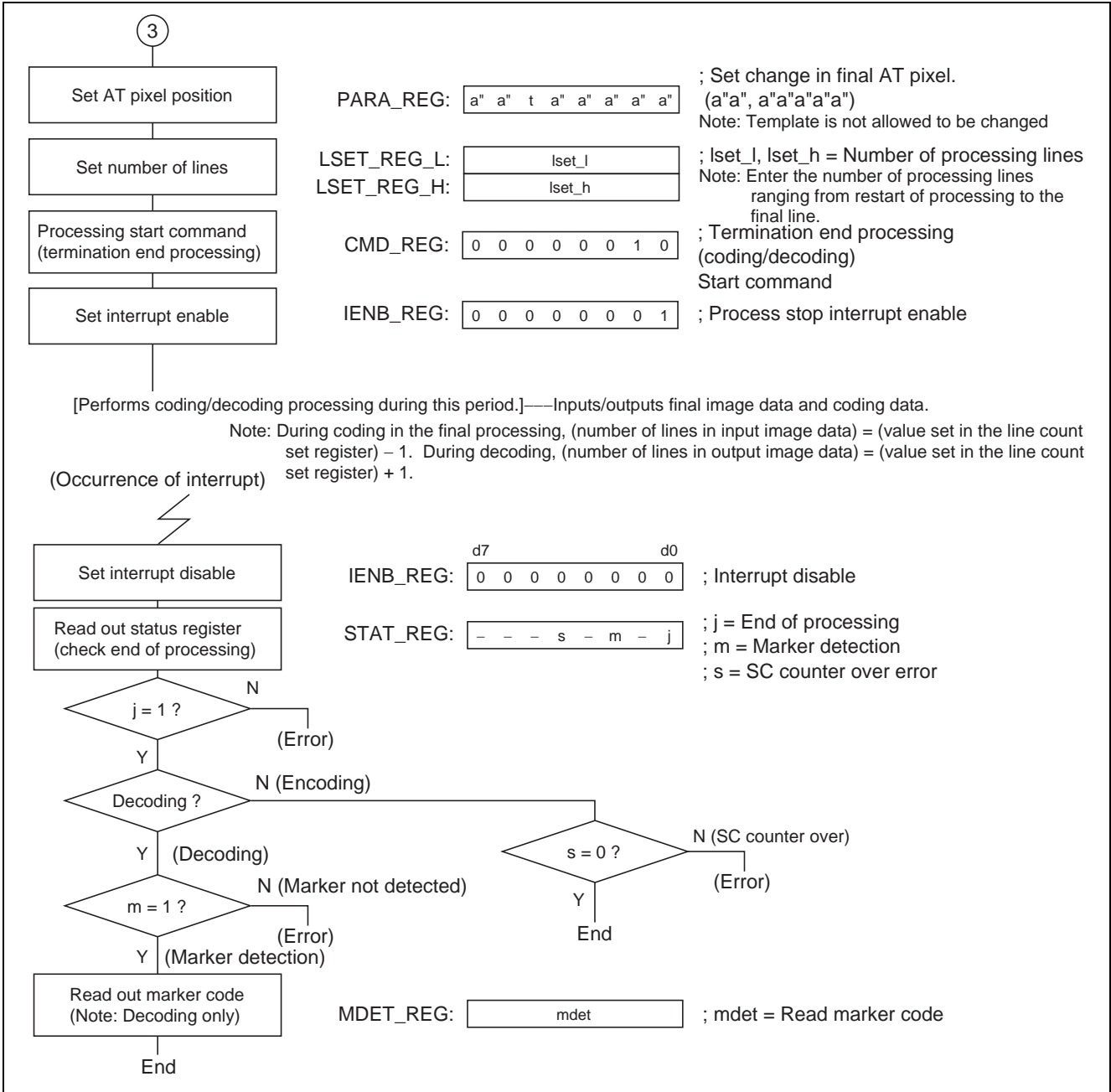
4. Register Setting Sequence

(1) Initialization sequence of built-in line memory and context table RAM

This sequence is used to carry out initialization sequence (0 clear) of context table RAM after the initialization ^(Note) of the built-in line memory by H/W reset.

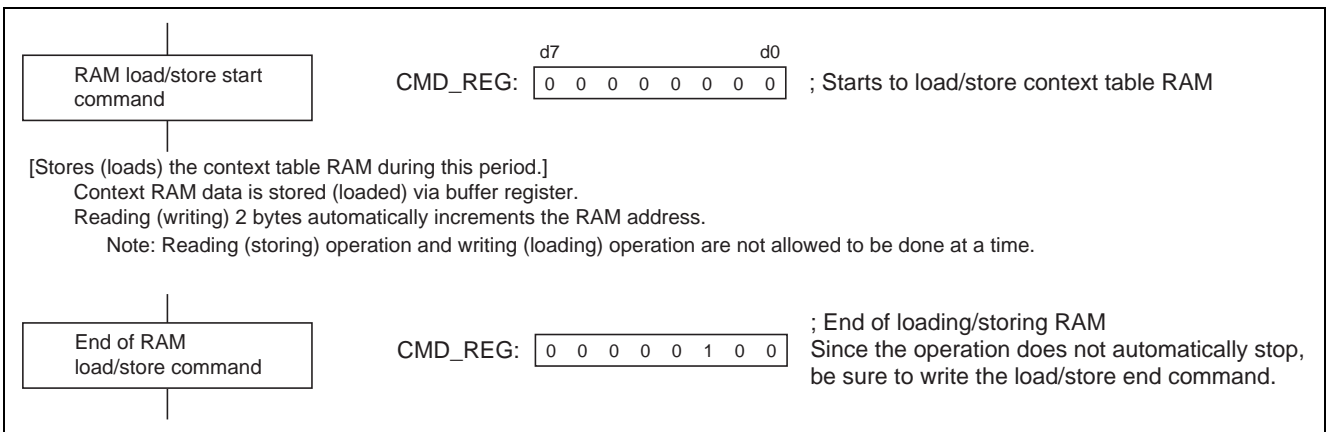
When the initialization is unnecessary (the contents of the current status table are directly used), this sequence is unnecessary.



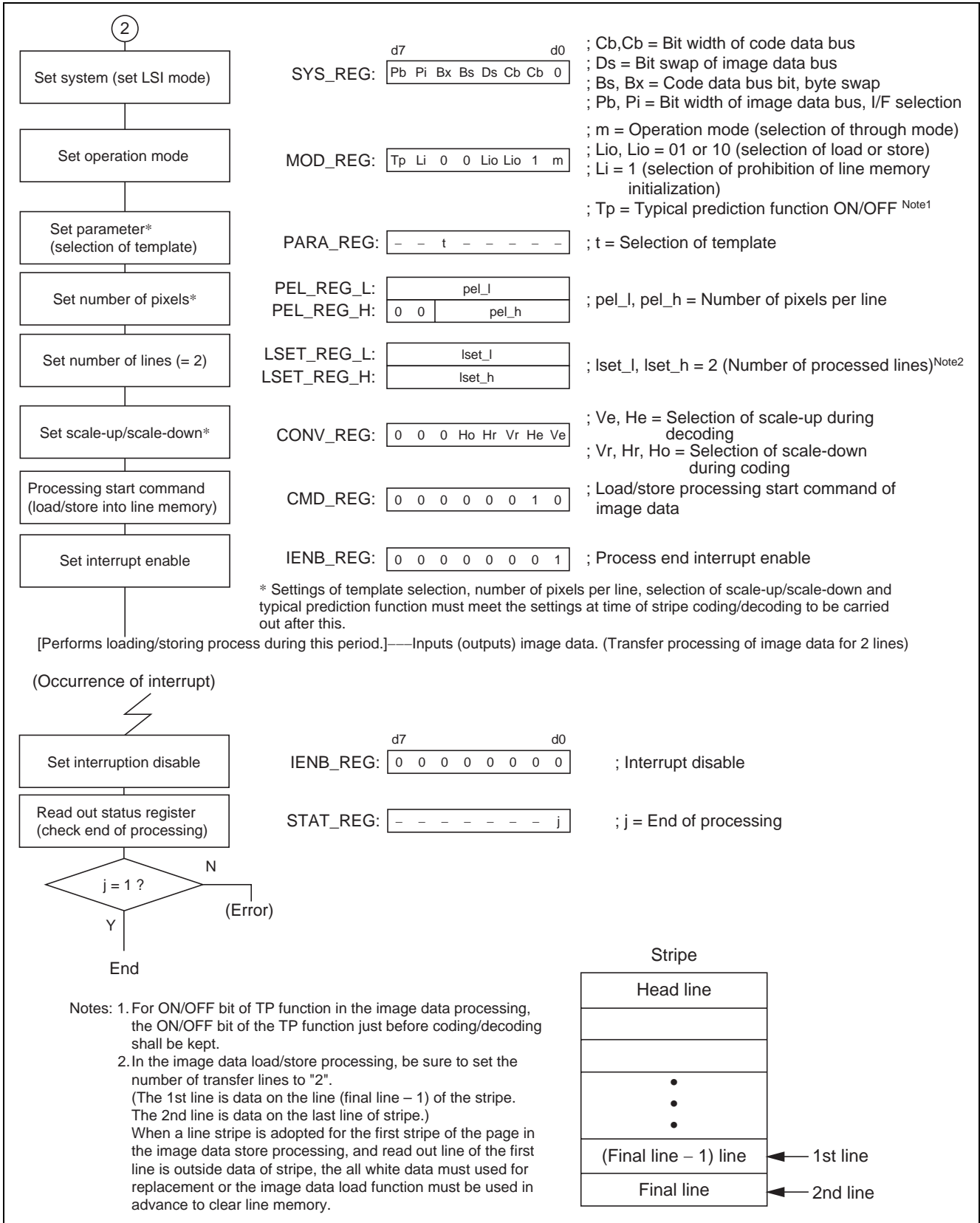


(4) Load/store processing sequence of the context table RAM

This sequence is used to load or store context table RAM.

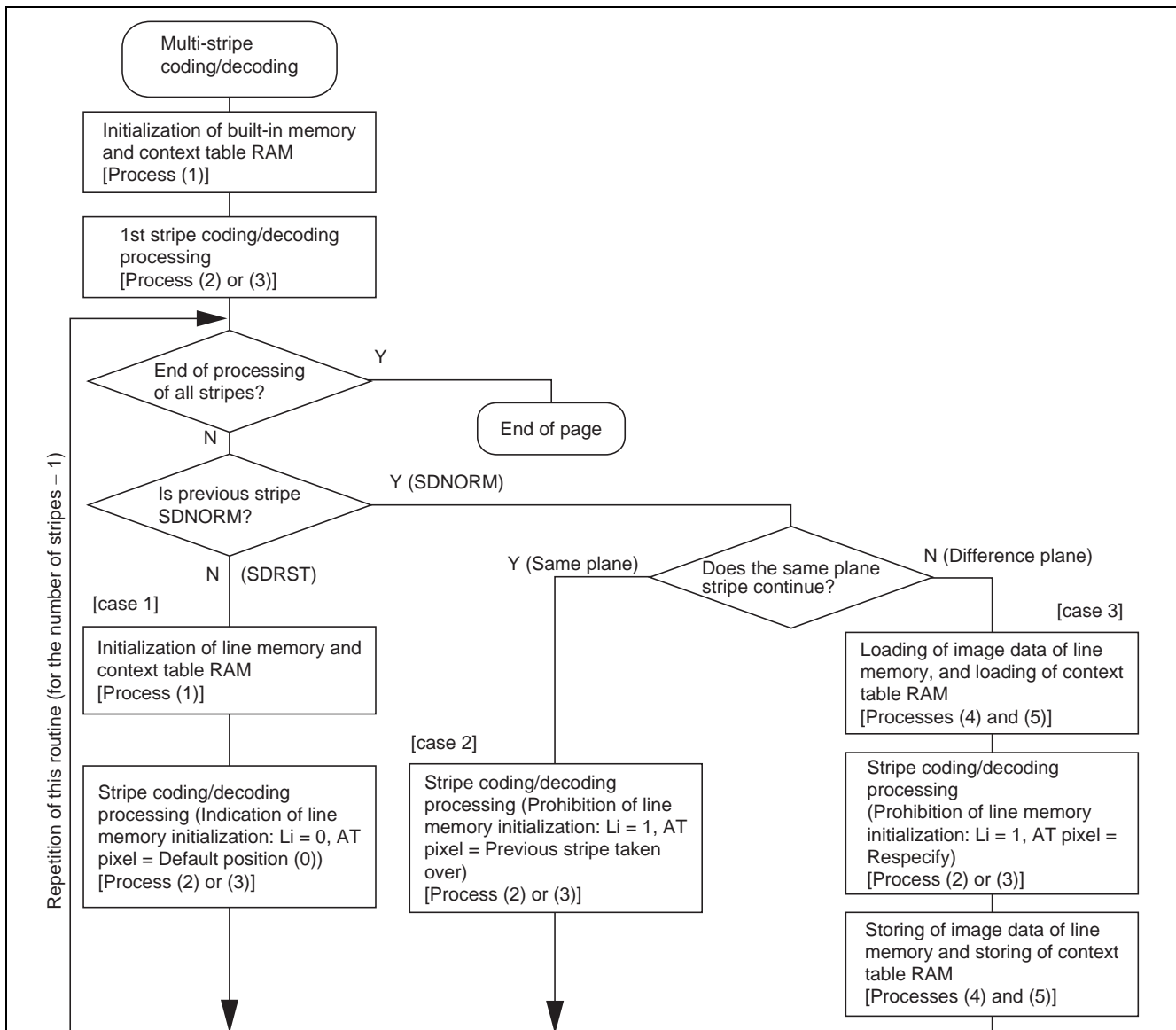


(5) Load/store processing sequence of line memory image data



(6) Total sequence of multi-stripe coding/decoding

For an image with a page consisting of more than one stripe or plane, coding or decoding process must be carried out in units of stripe after initialization.



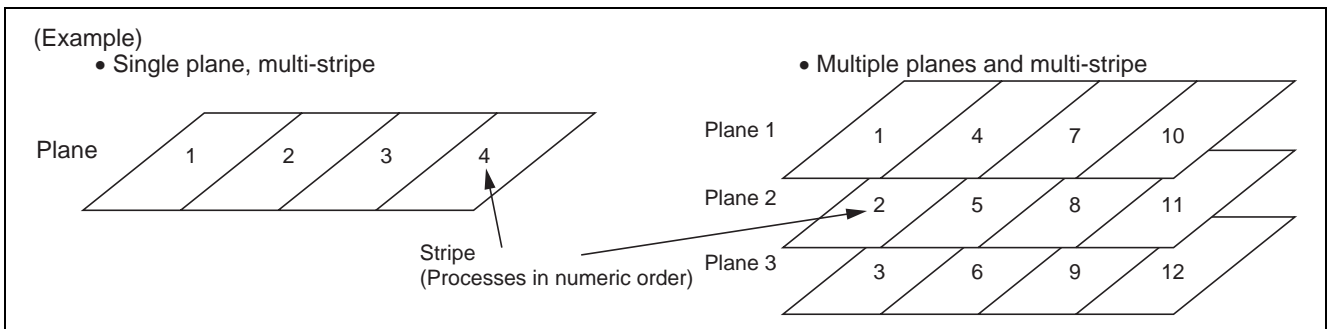
- Notes:
1. Since use of the host bus with 32-/16-bit bus during coding adopts word boundary, the end marker code may be followed by the pad bytes ("00") of 1 to 3-byte. These pad bytes must be removed outside. (see "Description on Register" (7))
 2. When decoding of stripes starts at time of decoding, the head coding data of SDE (stripe data entity) must be first entered. Read-through of head byte is indicated, if necessary. (At time of end of decoding stripes, the head block of coding data may be entered into LSI (FIFO) or may not be arranged in the word boundary. Management is therefore required outside.)
 3. The process of inter-stripe marker codes (ATMOVE, NEWLEN, etc.) (insert at time of coding and detection/removal at time of decoding) must be carried out outside.

Description

If the end marker of the previous stripe is SDRST, the status must be initialized for coding/decoding the next stripe. Start to carry out the process of next stripe by returning the AT pixel position to the default position after the initialization of built-in line memory and context table RAM. [case 1]

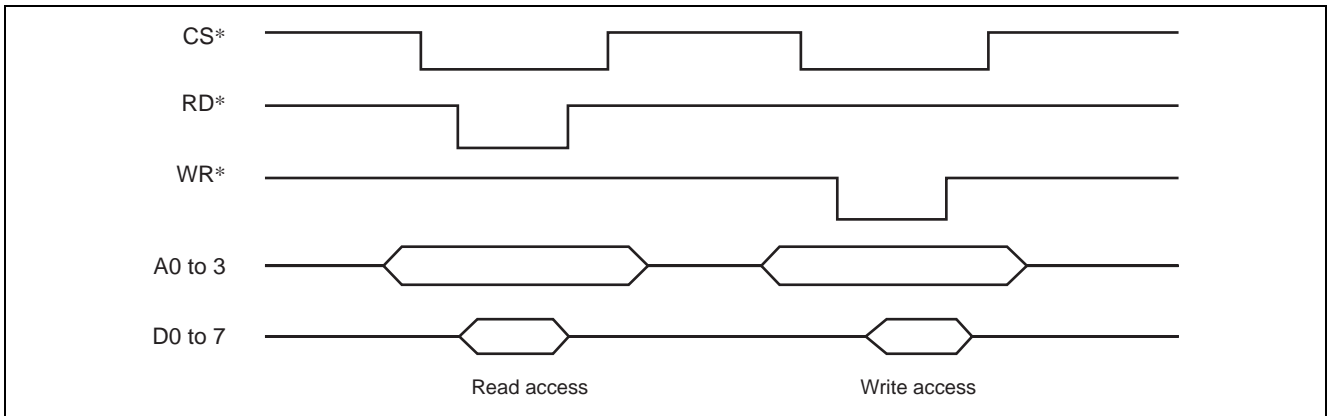
If the termination marker of the previous stripe is SDNORM, the status of the previous stripe must be taken over for coding/decoding the next stripe. If the stripe of the same plane is continuously coded/decoded, the AT pixel position takes over the final value of the previous stripe and the process of the next stripe is to start without initializing line memory and context table RAM to use the status of line memory and context table RAM at the end of previous stripe for the next stripe. [case 2]

On the other hand, since the status at the end of pre-stripe status of the same plane must be respecified for the status of line memory and context table RAM, line memory and context table RAM are to be loaded into LSI to respecify the AT pixel position and to start processing the next stripe when alternately coding/decoding stripes of different planes. After coding/decoding of stripe, save line memory and context table RAM for next stripe. [case 3]



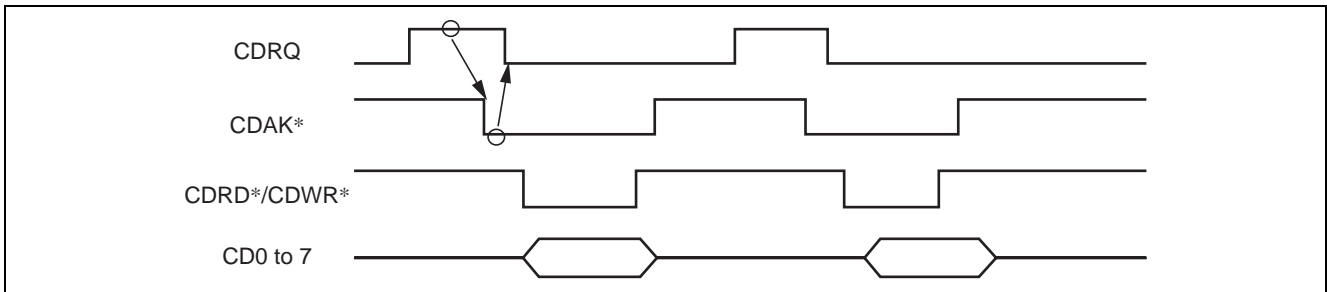
Timing Chart

1. Host Bus I/F

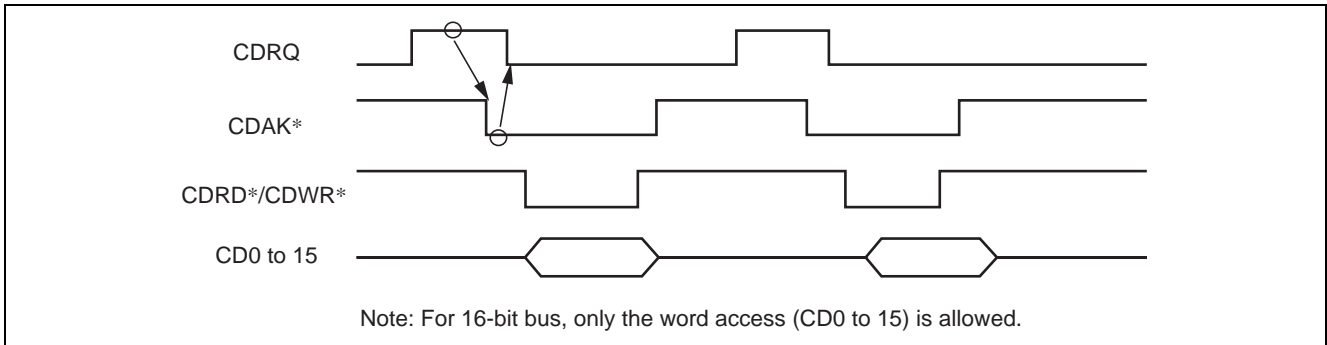


2. Code Data I/F

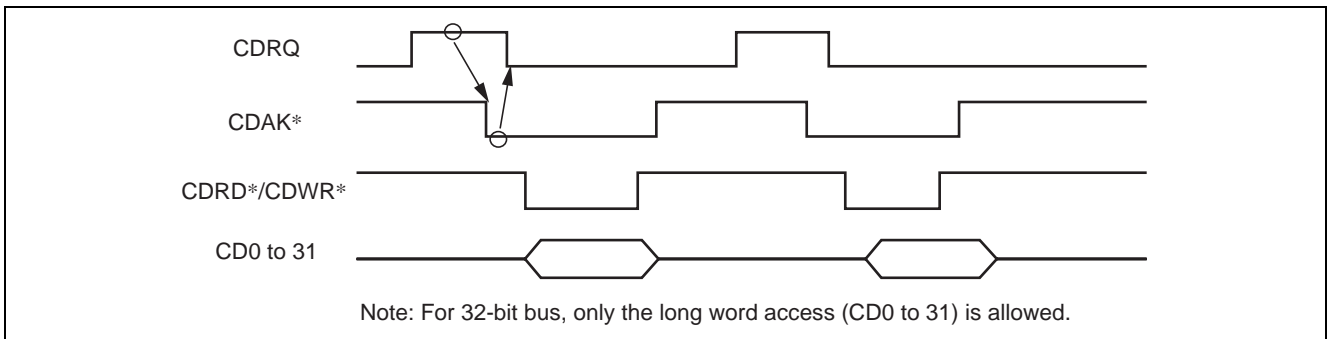
(a) For 8-bit bus



(b) For 16-bit bus



(c) For 32-bit bus



Description

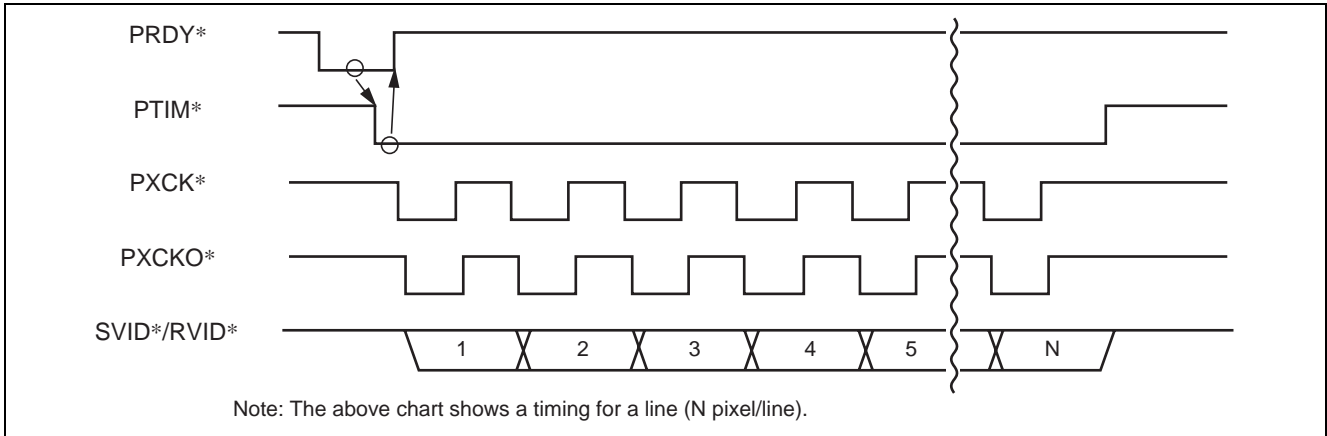
CDRQ can be checked for being asserted (H) to assert (L) CDAK*.

Asserting (L) CDAK* negates (L) CDRQ.

Asserting (L) section of CDRD*/CDWR* must be included in the CDAK* asserting section (L).

3. Image Data I/F

(1) Serial image data I/F



Description

PRDY* can be checked for being asserted (L) to assert (L) PTIM*.

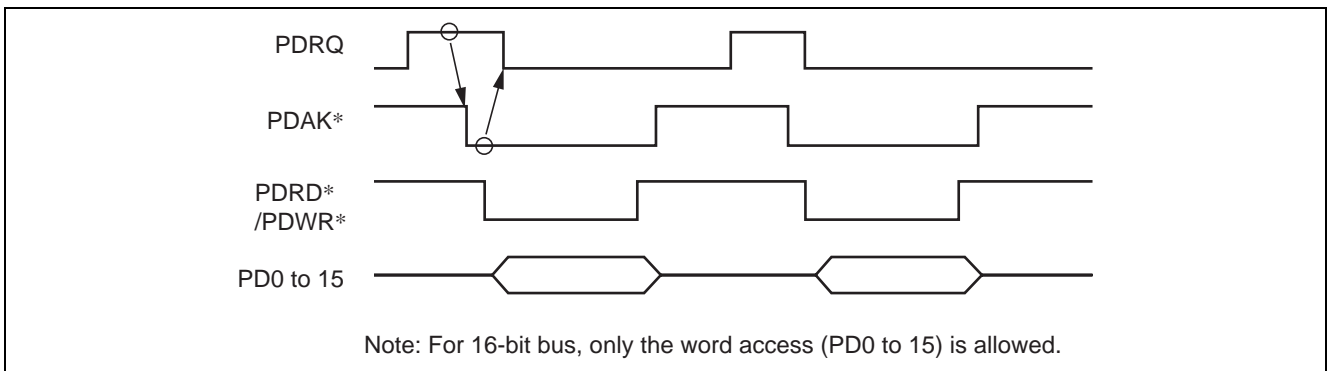
Asserting (L) PTIM* negates (H) PRDY*.

PXCKO* is an output of having gated PXCK* input with PTIM*.

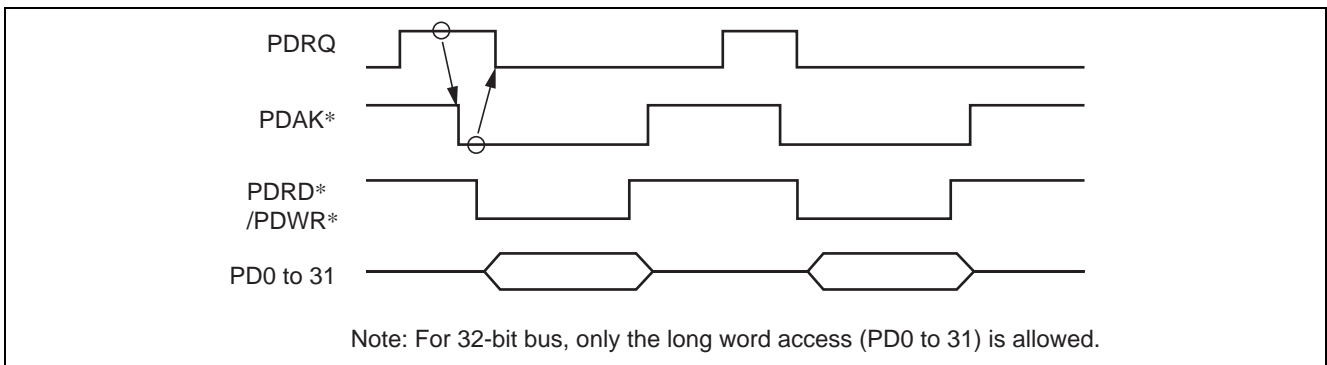
The image data (SVID*/RVID*) is input/output in synchronization with PXCK* or PXCKO*.

(2) Parallel image data I/F

(a) 16-bit bus



(b) 32-bit bus



Description

PDRQ can be checked for being asserted (H) to assert (L) PDAK*.

Asserting (L) PDAK* negates (H) PDRQ.

Asserting (L) section of PDRD*/PDWR* must be included in the asserting section (L) of PDAK*.

Examples of System Configuration

1. Example of Application for Digital PPC and Multifunctional FAX Machine

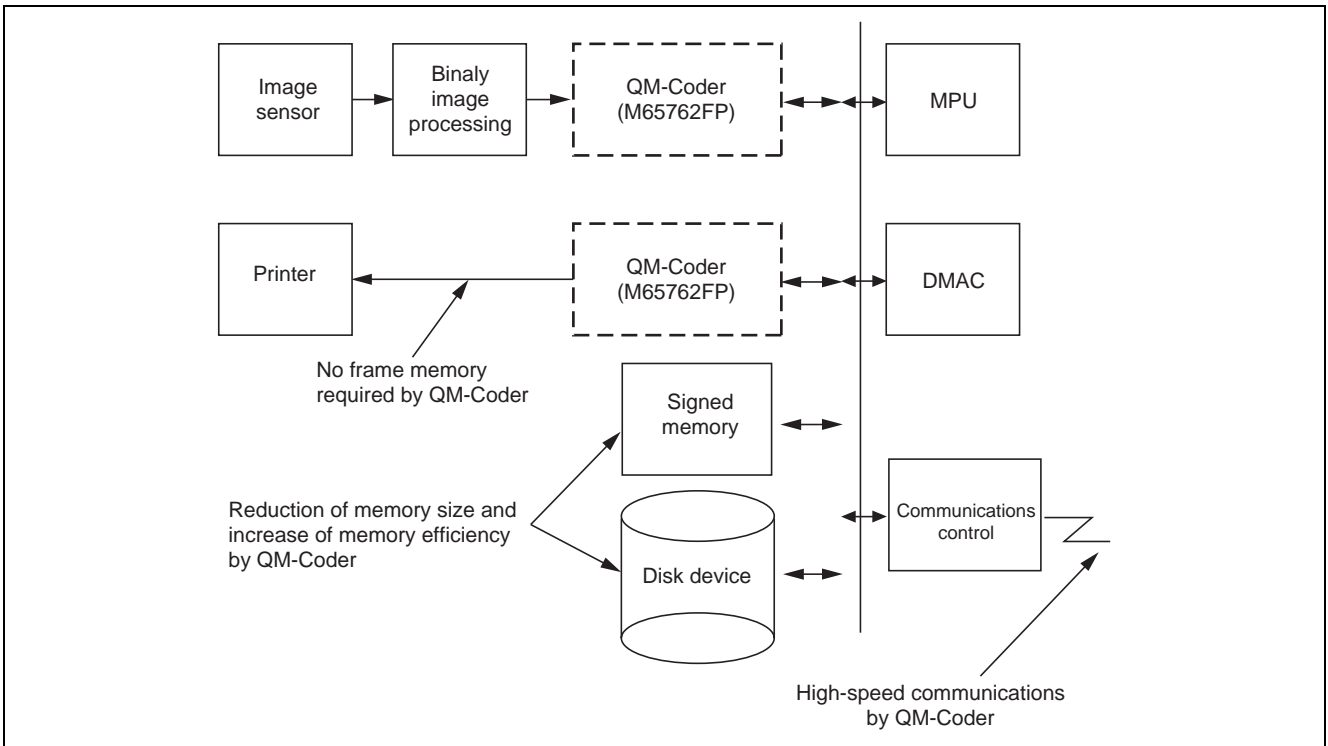


Figure 5 Example of Application for Digital PPC and Multifunctional FAX Machine

2. Example of Application for Printer

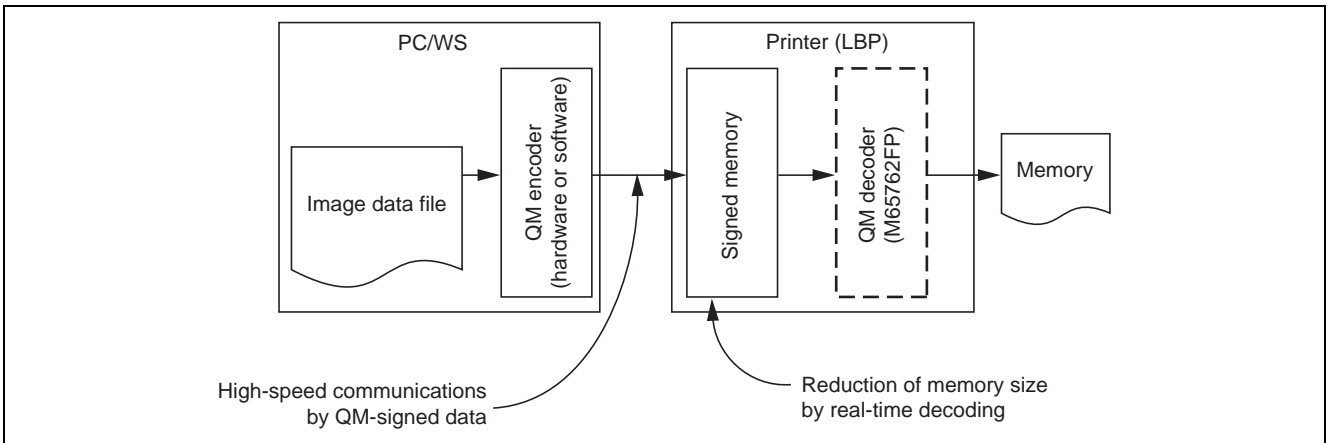


Figure 6 Example of Application for Printer

[Appendix A.1] JBIG Data Structure

B I E				; Bi-level Image Entity															
B I H				; Bi-level Image Header															
DL	1			; lowest resolution layer															
D	1			; final resolution layer															
P	1			; number of bit-planes															
-	1			; dummy 0															
X _D	4			; horizontal dimension at highest resolution															
Y _D	4			; vertical dimension at highest resolution															
L _D	4			; number of lines per stripe at lowest resolution															
M _x	1			; maximum horizontal offsets allowed for AT pixel															
M _y	1			; maximum vertical offsets allowed for AT pixel															
Order	1			; order byte															
-		b7-4		; dummy 0															
HITOLO		b3		; resolution-order distinction															
SEQ		b2		; progressive-versus-sequential distinction															
ILEAVE		b1		; interleaving of multiple bit-planes															
SMID		b0		; indexed over stripe is in middle															
Options 1				; option byte															
-		b7		; dummy 0															
LRLTWO		b6		; lowest resolution-layer two line template															
VLENGTH		b5		; NEWLEN (new vertical dimension) marker enable															
TPDON		b4		; differential-layer TP enable															
TPBON		b3		; lowest-resolution-layer TP enable															
DPON		b2		; DP enable															
DPPRIV		b1		; private DP table															
DPLAST		b0		; DP table last is to be reused															
DPTABLE	0/1728			; private DP table															
				(It is present only if DPON = 1, DPPRIV = 1, DPLAST = 0)															
B I D				; bi-level Image Data ((1) (2) x N)															
(1)	Floating Marker Segments ((a) ~ (c))																		
(a)	AT move marker																		
ESC	1			; FFh															
ATMOVE	1			; 06h															
Y _{AT}	4			; line in which an AT switch is to be made															
τ _x	1			; horizontal offset of the AT pixel															
τ _y	1			; vertical offset of the AT pixel															
(b)	new-length marker																		
ESC	1			; FFh															
NEWLEN	1			; 05h															
Y _D	4			; new Y _D															
(c)	comment marker																		
ESC	1			; FFh															
COMMENT	1			; 07h															
L _c	4			; length in bytes of private comment															
comment	L _c			; contents of comment															
(2)	SDE			; Stripe Data Entry (Within the frame: LSI support range)															
<table border="0"> <tr> <td>PSCD</td> <td></td> <td></td> <td></td> <td>; Protected Stripe Coded Data = byte stuffed SCD (Stripe Code Data)</td> </tr> <tr> <td>ESC</td> <td>1</td> <td></td> <td></td> <td>; FFh</td> </tr> <tr> <td>SDNORM/SDRST</td> <td>1</td> <td></td> <td></td> <td>; normal terminate (02h) ; /reset "state" for next SDE (03h)</td> </tr> </table>					PSCD				; Protected Stripe Coded Data = byte stuffed SCD (Stripe Code Data)	ESC	1			; FFh	SDNORM/SDRST	1			; normal terminate (02h) ; /reset "state" for next SDE (03h)
PSCD				; Protected Stripe Coded Data = byte stuffed SCD (Stripe Code Data)															
ESC	1			; FFh															
SDNORM/SDRST	1			; normal terminate (02h) ; /reset "state" for next SDE (03h)															

abort BID marker																			
ESC	1			; FFh															
ABORT	1			; 04h															
reserved marker																			
ESC	1			; FFh															
RESERVE	1			; 01h															

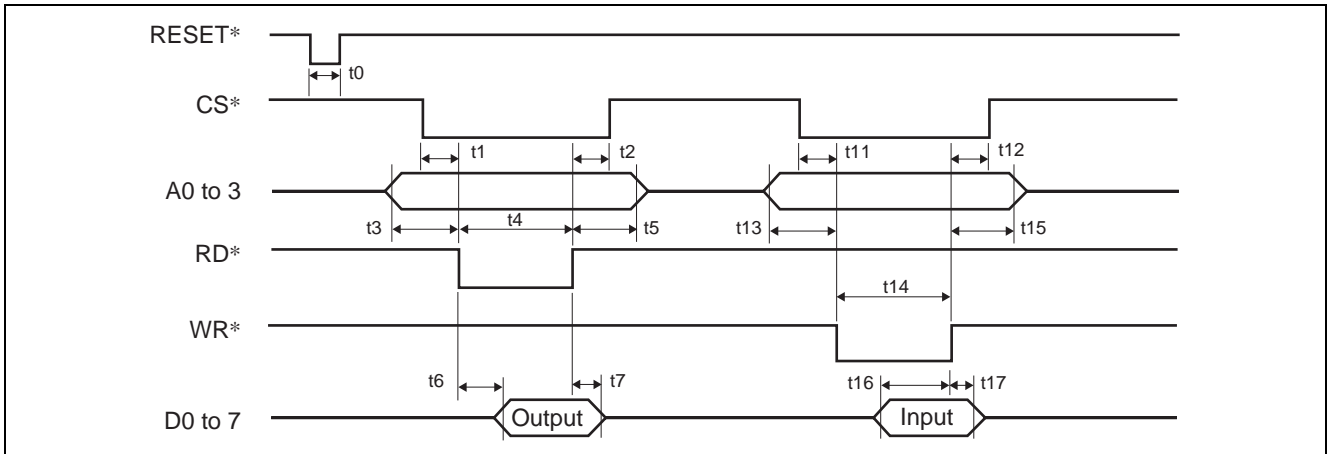
[Appendix A.2] JBIG Probability Estimation Table

ST	LSZ	NLPS	NMPS	SWTCH	ST	LSZ	NLPS	NMPS	SWTCH
0	0x5ald	1	1	1	57	0x01a4	55	58	0
1	0x2586	14	2	0	58	0x0160	56	59	0
2	0x1114	16	3	0	59	0x0125	57	60	0
3	0x080b	18	4	0	60	0x00f6	58	61	0
4	0x03d8	20	5	0	61	0x00cb	59	62	0
5	0x01da	23	6	0	62	0x00ab	61	63	0
6	0x00e5	25	7	0	63	0x008f	61	32	0
7	0x006f	28	8	0	64	0x5b12	65	65	1
8	0x0036	30	9	0	65	0x4d04	80	66	0
9	0x001a	33	10	0	66	0x412c	81	67	0
10	0x000d	35	11	0	67	0x37d8	82	68	0
11	0x0006	9	12	0	68	0x2fe8	83	69	0
12	0x0003	10	13	0	69	0x293c	84	70	0
13	0x0001	12	13	0	70	0x2379	86	71	0
14	0x5a7f	15	15	1	71	0x1edf	87	72	0
15	0x3f25	36	16	0	72	0x1aa9	87	73	0
16	0x2cf2	38	17	0	73	0x174e	72	74	0
17	0x207c	39	18	0	74	0x1424	72	75	0
18	0x17b9	40	19	0	75	0x119c	74	76	0
19	0x1182	42	20	0	76	0x0f6b	74	77	0
20	0x0cef	43	21	0	77	0x0d51	75	78	0
21	0x09a1	45	22	0	78	0x0bb6	77	79	0
22	0x072f	46	23	0	79	0x0a40	77	48	0
23	0x055c	48	24	0	80	0x5832	80	81	1
24	0x0406	49	25	0	81	0x4d1c	88	82	0
25	0x0303	51	26	0	82	0x438e	89	83	0
26	0x0240	52	27	0	83	0x3bdd	90	84	0
27	0x01b1	54	28	0	84	0x34ee	91	85	0
28	0x0144	56	29	0	85	0x2eae	92	86	0
29	0x00f5	57	30	0	86	0x299a	93	87	0
30	0x00b7	59	31	0	87	0x2516	86	71	0
31	0x008a	60	32	0	88	0x5570	88	89	1
32	0x0068	62	33	0	89	0x4ca9	95	90	0
33	0x004e	63	34	0	90	0x44d9	96	91	0
34	0x003b	32	35	0	91	0x3e22	97	92	0
35	0x002c	33	9	0	92	0x3824	99	93	0
36	0x5ae1	37	37	1	93	0x32b4	99	94	0
37	0x484c	64	38	0	94	0x2e17	93	86	0
38	0x3a0d	65	39	0	95	0x56a8	95	96	1
39	0x2ef1	67	40	0	96	0x4f46	101	97	0
40	0x261f	68	41	0	97	0x47e5	102	98	0
41	0x1f33	69	42	0	98	0x41cf	103	99	0
42	0x19a8	70	43	0	99	0x3c3d	104	100	0
43	0x1518	72	44	0	100	0x375e	99	93	0
44	0x1177	73	45	0	101	0x5231	105	102	0
45	0x0e74	74	46	0	102	0x4c0f	106	103	0
46	0x0bfb	75	47	0	103	0x4639	107	104	0
47	0x09f8	77	48	0	104	0x415e	103	99	0
48	0x0861	78	49	0	105	0x5627	105	106	1
49	0x0706	79	50	0	106	0x50e7	108	107	0
50	0x05cd	48	51	0	107	0x4b85	109	103	0
51	0x04de	50	52	0	108	0x5597	110	109	0
52	0x040f	50	53	0	109	0x504f	111	107	0
53	0x0363	51	54	0	110	0x5a10	110	111	1
54	0x02d4	52	55	0	111	0x5522	112	109	0
55	0x025c	53	56	0	112	0x59eb	112	111	1
56	0x01f8	54	57	0					

[Appendix B] Timing Characteristics

(Conditions: $V_{DD} = 5\text{ V} \pm 5\%$, $C = 50\text{ pF}$, $T_a = 0\text{ to }70^\circ\text{C}$)

1. Host Bus I/F



2. Code Data I/F

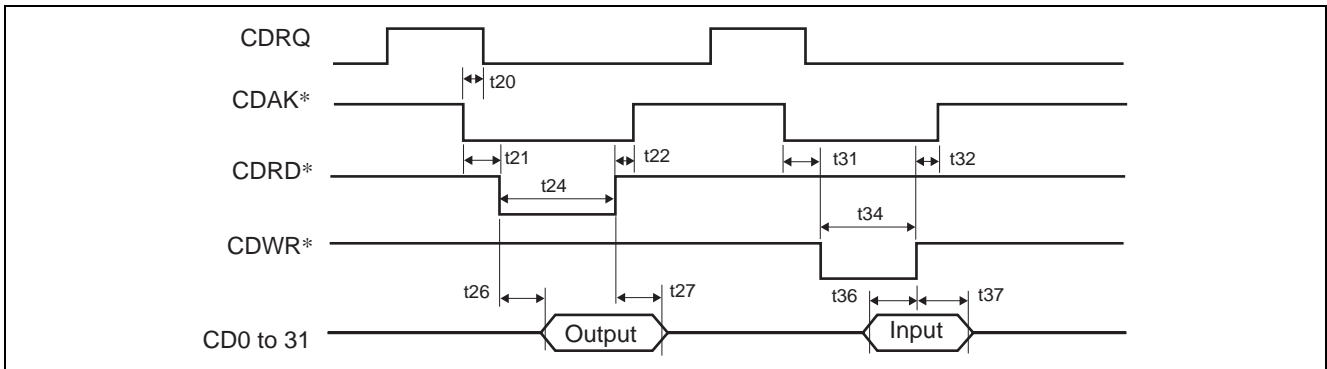


Table B.1 Host Bus I/F Timing Characteristics

(Unit: ns)

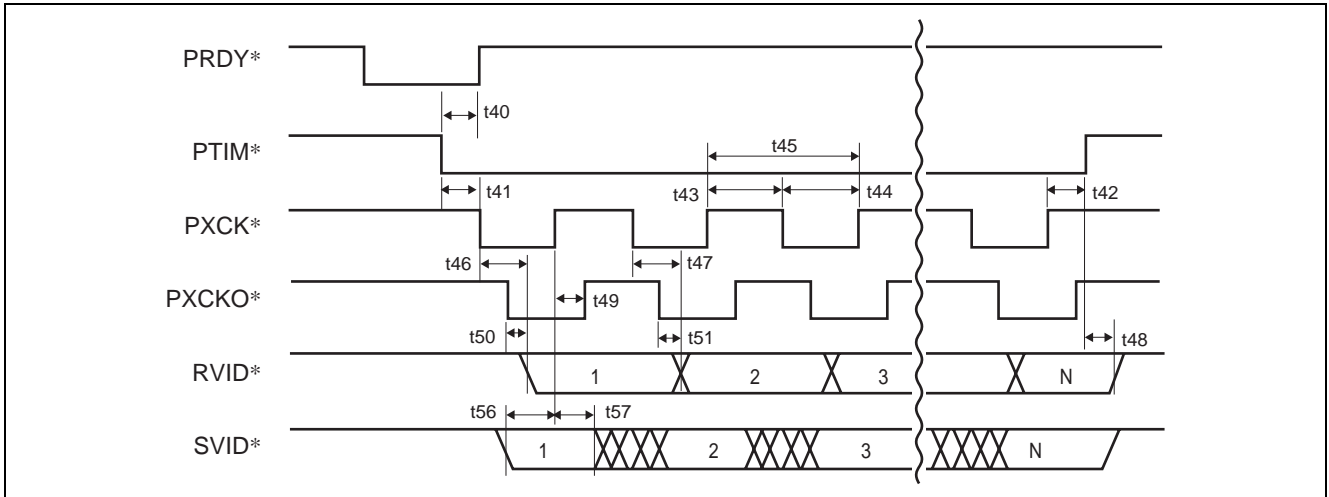
Abbreviation	Item	Timing Conditions		
		Min	Typ	Max
t0	RESET* assert time	100	—	—
t1	CS* setup time to RD* assert	15	—	—
t2	CS* hold time to RD* negate	15	—	—
t3	A0 to 3 setup time to RD* assert	15	—	—
t4	RD* assert time	20	—	—
t5	A0 to 3 hold time to RD* negate	15	—	—
t6	D0 to 7 output determination time to RD* assert	0	—	20
t7	D0 to 7 output hold time to RD* negate	0	—	20
t11	CS* setup time to WR* assert	15	—	—
t12	CS* hold time to WR* negate	15	—	—
t13	A0 to 3 setup time to WR* assert	15	—	—
t14	WR* assert time	15	—	—
t15	A0 to 3 hold time to WR* negate	15	—	—
t16	D0 to 7 input setup time to WR* negate	20	—	—
t17	D0 to 7 input hold time to WR* negate	5	—	—

Table B.2 Timing Characteristics of Code Data Bus I/F

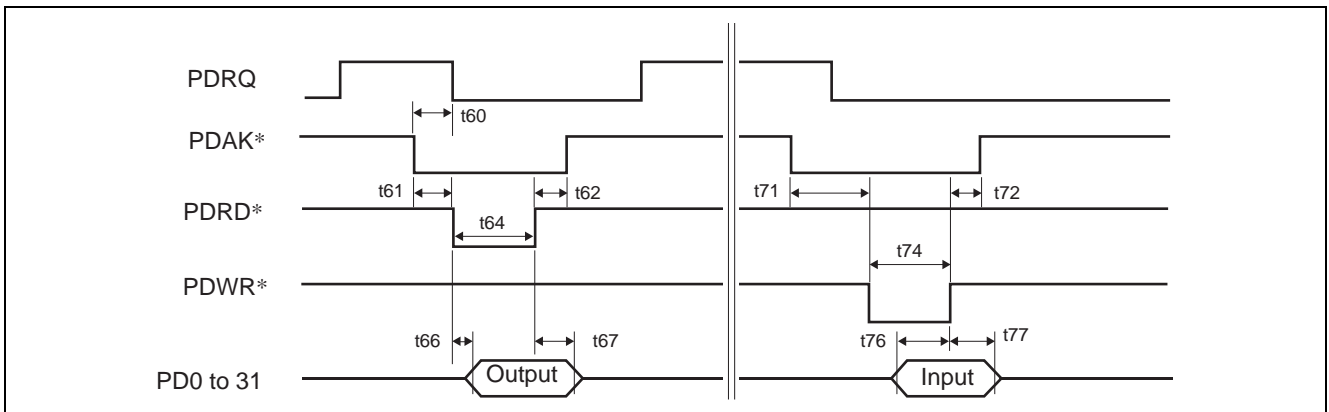
Abbreviation	Item	Timing Conditions		
		Min	Typ	Max
t20	CDRQ negate time to CDAK* assert	—	—	15
t21	CDAK* setup time to CDRD* assert	15	—	—
t22	CDAK* hold time to CDRD* negate	15	—	—
t24	CDRD* assert time	20	—	—
t26	CD0 to 31 output determination time to CDRD* assert	0	—	20
t27	CD0 to 31 output hold time to CDRD* negate	0	—	20
t31	CDAK* setup time to CDWR* assert	15	—	—
t32	CDAK* hold time to CDWR* negate	15	—	—
t34	CDWR* assert time	15	—	—
t36	CD0 to 31 input setup time to CDWR* negate	15	—	—
t37	CD0 to 31 input hold time to CDWR* negate	5	—	—

3. Image Data I/F

(1) Serial image data I/F



(2) Parallel image data I/F



4. Master Clock Input Frequency (LSI Operating Frequency)

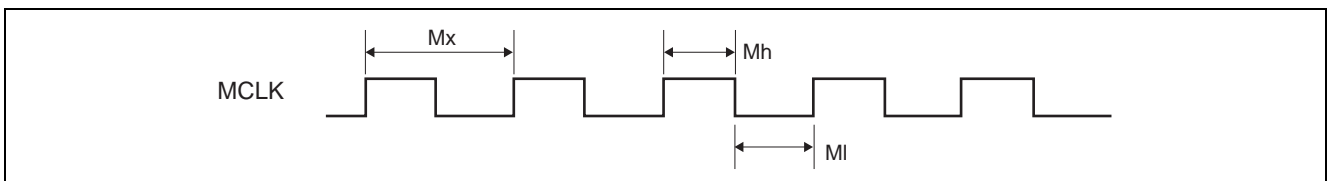


Table B.3 Timing Characteristics of Image Data I/F

(Unit: ns)

Abbreviation	Item	Timing Conditions		
		Min	Typ	Max
t40	PRDY* negate time to PTIM* assert	—	—	20
t41	PTIM* setup time to PXCK* fall	15	—	—
t42	PTIM* hold time to PXCK* rise	15	—	—
t43	PXCK* high time	10	—	—
t44	PXCK* low time	10	—	—
t45	PXCK* cycle	25	—	—
t46	RVID* output determination time to PXCK* fall	—	—	20
t47	RVID* output change time to PXCK* fall	—	—	20
t48	RVID* negate time to PTIM* negate	0	—	—
t49	PXCKO* delay time to PXCK*	—	—	10
t50	RVID* output determination time to PXCKO* fall	—	—	12
t51	RVID* output change time to PXCKO* fall	—	—	12
t56	SVID* setup time to PXCK* rise	10	—	—
t57	SVID* hold time to PXCK* rise	10	—	—
t60	PDRQ negate time to PDAK* assert	—	—	15
t61	PDAK* setup time to PDRD* assert	15	—	—
t62	PDAK* hold time to PDRD* negate	15	—	—
t64	PDRD* assert time	20	—	—
t66	PD0 to 31 output determination time to PDRD* assert	0	—	20
t67	PD0 to 31 output hold time to PDRD* negate	0	—	20
t71	PDAK* setup time to PDWR* assert	15	—	—
t72	PDAK* hold time to PDWR* negate	15	—	—
t74	PDWR* assert time	15	—	—
t76	PD0 to 31 input setup time to PDWR* negate	15	—	—
t77	PD0 to 31 input hold time to PDWR* negate	5	—	—

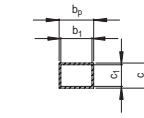
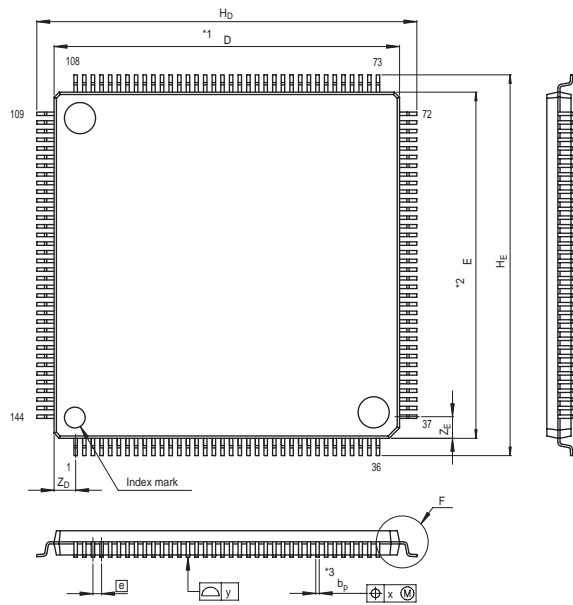
Table B.4 Master Clock Frequencies

(Unit: ns)

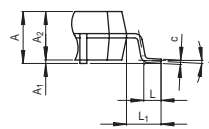
Item	Timing Conditions			Max Frequency
	Min	Typ	Max	
MCLK cycle (Mx)	25	—	—	40 MHz
MCLK high level time (Mh)	10	—	—	
MCLK low level time (Ml)	10	—	—	

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP144-20x20-0.50	PLQP0144KA-A	144P6Q-A / FP-144L / FP-144LV	1.2g



Terminal cross section



Detail F

NOTE)
 1. DIMENSIONS **1* AND **2* DO NOT INCLUDE MOLD FLASH.
 2. DIMENSION **3* DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	19.9	20.0	20.1
E	19.9	20.0	20.1
A ₂	—	1.4	—
H _D	21.8	22.0	22.2
H _E	21.8	22.0	22.2
A	—	—	1.7
A ₁	0.05	0.1	0.15
b _p	0.17	0.22	0.27
b ₁	—	0.20	—
c	0.09	0.145	0.20
c ₁	—	0.125	—
θ	0°	—	8°
[e]	—	0.5	—
x	—	—	0.08
y	—	—	0.10
Z _D	—	1.25	—
Z _E	—	1.25	—
L	0.35	0.5	0.65
L ₁	—	1.0	—

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